8-bit Microcontrollers

New 8FX MB95560H/570H/580H Series

MB95F562H/F562K/F563H/F563K/F564H/F564K MB95F572H/F572K/F573H/F573K/F574H/F574K MB95F582H/F582K/F583H/F583K/F584H/F584K

DESCRIPTION

The MB95560H/570H/580H Series are three series of general-purpose, single-chip microcontrollers. In addition to a compact instruction set, the microcontrollers of these series contain a variety of peripheral resources.

■ FEATURES

- F²MC-8FX CPU core
 - Instruction set optimized for controllers
 - Multiplication and division instructions
 - 16-bit arithmetic operations
 - Bit test branch instructions
 - Bit manipulation instructions, etc.
- Note: F²MC is the abbreviation of FUJITSU Flexible Microcontroller.
- Clock (The main oscillation clock and the suboscillation clock are only available on MB95F562H/F562K/ F563H/F563K/F564H/F564K/F582H/F582K/F583H/F583K/F584H/F584K.)
 - Selectable main clock source Main oscillation clock (up to 16.25 MHz, maximum machine clock frequency: 8.125 MHz) External clock (up to 32.5 MHz, maximum machine clock frequency: 16.25 MHz) Main CR clock (4 MHz \pm 2%)
 - The main CR clock frequency becomes 8 MHz when the PLL multiplier is 2.
 The main CR clock frequency becomes 10 MHz when the PLL multiplier is 2.5.
 The main CR clock frequency becomes 12 MHz when the PLL multiplier is 3.
 The main CR clock frequency becomes 16 MHz when the PLL multiplier is 4.
 Selectable subclock source
 - Suboscillation clock (32.768 kHz) External clock (32.768 kHz) Sub-CR clock (Typ: 100 kHz, Min: 50 kHz, Max: 150 kHz)
- Timer
 - + 8/16-bit composite timer \times 2 channels (only one channel on MB95F572H/F572K/F573H/F573K/F574H/ F574K)
 - Time-base timer \times 1 channel
 - Watch prescaler \times 1 channel

(Continued)

For the information for microcontroller supports, see the following website.

http://edevice.fujitsu.com/micom/en-support/



- LIN-UART (only available on MB95F562H/F562K/F563H/F563K/F564H/F564K/F582H/F582K/F583H/ F583K/F584H/F584K)
 - Full duplex double buffer
 - · Capable of clock-synchronized serial data transfer and clock-asynchronized serial data transfer
- External interrupt
 - Interrupt by edge detection (rising edge, falling edge, and both edges can be selected)
 - Can be used to wake up the device from different low power consumption (standby) modes
- 8/10-bit A/D converter
 - 8-bit or 10-bit resolution can be selected.
- Low power consumption (standby) modes
 - There are four standby modes as follows:
 - Stop mode
 - Sleep mode
 - Watch mode
 - Time-base timer mode
 - In standby mode, the device can be made to enter either normal standby mode or deep standby mode.
- I/O port
 - MB95F562H/F563H/F564H (maximum no. of I/O ports: 16) General-purpose I/O ports (N-ch open drain) : 1 General-purpose I/O ports (CMOS I/O) : 15
 - MB95F562K/F563K/F564K (maximum no. of I/O ports: 17) General-purpose I/O ports (N-ch open drain) : 2 General-purpose I/O ports (CMOS I/O) : 15
 - MB95F572H/F573H/F574H (maximum no. of I/O ports: 4) General-purpose I/O ports (N-ch open drain) : 1 General-purpose I/O ports (CMOS I/O) : 3
 - MB95F572K/F573K/F574K (maximum no. of I/O ports: 5) General-purpose I/O ports (N-ch open drain) : 2 General-purpose I/O ports (CMOS I/O) : 3
 - MB95F582H/F583H/F584H (maximum no. of I/O ports: 12) General-purpose I/O ports (N-ch open drain) : 1 General-purpose I/O ports (CMOS I/O) : 11
 - MB95F582K/F583K/F584K (maximum no. of I/O ports: 13) General-purpose I/O ports (N-ch open drain) : 2 General-purpose I/O ports (CMOS I/O) : 11
- On-chip debug
 - 1-wire serial control
 - Serial writing supported (asynchronous mode)
- Hardware/software watchdog timer
 - Built-in hardware watchdog timer
 - Built-in software watchdog timer
- Power-on reset
 - A power-on reset is generated when the power is switched on.
- Low-voltage detection reset circuit (only available on MB95F562K/F563K/F564K/F572K/F573K/F574K/ F582K/F583K/F584K)
 - Built-in low-voltage detector
- Clock supervisor counter
 - Built-in clock supervisor counter function
- Dual operation Flash memory
 - The program/erase operation and the read operat.ion can be executed in different banks (upper bank/lower bank) simultaneously.
- · Flash memory security function
 - Protects the content of the Flash memory.

■ PRODUCT LINE-UP

٠	MB95560H Series	

Part number										
	MB95F562H	MB95F563H	MB95F564H	MB95F562K	MB95F563K	MB95F564K				
Parameter										
Туре			Flash mem	ory product						
Clock supervisor	It cuponvisos th	o main clock or	soillation							
counter	n supervises in	supervises the main clock oscillation.								
Flash memory										
capacity	8 Kbyte	8 Kbyte 12 Kbyte 20 Kbyte 8 Kbyte 12 Kbyte 20 K								
RAM capacity	240 bytes	496 bytes	496 bytes	240 bytes	496 bytes	496 bytes				
Power-on reset			Y	es						
Low-voltage		NLa			Maa					
detection reset		No			Yes					
Reset input		Dedicated		Selec	ted through sof	tware				
	 Number of bat 	asic instructions	: 136							
	 Instruction bit 	•	: 8 bits							
CPU functions		Instruction length : 1 to 3 bytes								
		 Data bit length : 1, 8 and 16 bits Minimum instruction execution time : 61.5 ns (machine clock frequency = 16.25 MHz) 								
					ck frequency = 16					
	 Interrupt proc I/O ports (Mathematical Action 1) 		. 0.0 µs	 I/O ports (Ma 	1 1	5.25 MITZ)				
General-	 I/O ports (Ma CMOS I/O 	: 15		 CMOS I/O 	: 15					
purpose I/O	 N-ch open dr 			 N-ch open dr 	-					
Time-base timer	•		s (external clock							
Hardware/	 Reset general 									
software			MHz: 105 ms (Min)						
watchdog timer					ardware watchd	log timer.				
Wild register	It can be used	to replace 3 byt	es of data.							
	 A wide range 	of communicat	ion speed can b	e selected by a	a dedicated relo	ad timer.				
	It has a full duplex double buffer.									
LIN-UART	Clock-synchronized serial data transfer and clock-asynchronized serial data transfer is en-									
	abled.The LIN function can be used as a LIN master or a LIN slave.									
		tion can be use	d as a LIN mas	er or a LIN slav	'e.					
8/10-bit A/D	6 channels									
converter		esolution can be	e selected.							
	2 channels									
8/16-bit					or a "16-bit tim					
composite timer	 It has the following functions: interval timer function, PWC function, PWM function and input contrast function 									
composite amer	capture function.Count clock: it can be selected from internal clocks (seven types) and external clocks.									
	 It can output square wave. 									
	6 channels									
External		dae detection (The risina edge	, falling edge, o	r both edges ca	n be selected.)				
interrupt		•	e device from th		•					
On-chip debug	 1-wire serial 									
	l	erial writing (asy								

Part number Parameter	MB95F562H	MB95F563H	MB95F56	64H	MB95	F562K	MB9	95F563K	MB95F564K
Watch prescaler	Eight different t	ime intervals ca	an be selec	cted.					
Flash memory	suspend/eras It has a flag in Flash security Number of								
Standby mode	Sleep mode, st	op mode, watcł	n mode, tin	ne-ba	se time	er mode			
Package			FI	PT-20	2P-M19)P-M09)P-M10				

• MB95570H Series

MB95F572H	MB95F573H	MB95F574H	H MB9	5F572K	MB95F573K	MB95F574K			
	Flash memory product								
supervises the main clock oscillation.									
8 Kbyte	12 Kbyte	20 Kbyte	8 4	Kbyte	12 Kbyte	20 Kbyte			
240 bytes	496 bytes	496 bytes	240	bytes	496 bytes	496 bytes			
			Yes						
	No				Yes				
	Dedicated			Select	ted through sof	tware			
 Instruction bit Instruction ler Data bit lengt Minimum inst 	length ngth h ruction executic	: 8 bi : 1 tc : 1, 8 : 1, 8	ts 3 bytes and 16 b 5 ns (mac	hine cloc					
CMOS I/O	: 3		• CMC	DS I/Ò	´:3				
nterval time: 0.	256 ms to 8.3 s	(external clo	ock freque	ency = 4 M	MHz)				
Main oscillat The sub-CR of	ion clock at 10 clock can be use	ed as the sou		of the ha	ardware watchd	log timer.			
	solution can be	e selected.							
 The timer can It has the follocapture function Count clock: i It can output set 	wing functions: on. t can be selecte	interval time	r function,	, PWC fur	nction, PWM fur	nction and input			
					both edges ca	n be selected.)			
		nchronous m	node).						
Eight different t	ime intervals ca	in be selecte	d.						
 It supports automatic programming (Embedded Algorithm) and program/erase/erase-suspend/erase-resume commands. It has a flag indicating the completion of the operation of Embedded Algorithm. Flash security feature for protecting the content of the Flash memory 									
	-	-	0 years	10 yea	rs 5 years	7			
			-						
		DIP	-8P-M03						
	Number of ba Instruction bit Instruction ler Data bit lengt Minimum inst Interrupt proc I/O ports (Mar CMOS I/O N-ch open dra nterval time: 0. Reset genera Main oscillat The sub-CR of t can be used t No LIN-UART channels 3-bit or 10-bit re channel The timer can It has the follo capture functi Count clock: i It can output s channels Interrupt by ea I can be used 1-wire serial of It supports a suspend/eras It has a flag ir Flash security Number of p Data retenti	No Dedicated Number of basic instructions Instruction bit length Instruction length Data bit length Minimum instruction execution Interrupt processing time I/O ports (Max) : 4 CMOS I/O : 3 N-ch open drain: 1 Interval time: 0.256 ms to 8.3 s Reset generation cycle Main oscillation clock at 10 The sub-CR clock can be used t can be used to replace 3 byte No LIN-UART 2 channels 3-bit or 10-bit resolution can be channel The timer can be configured It has the following functions: capture function. Count clock: it can be selected It can output square wave. 2 channels Interrupt by edge detection (It supports serial writing (asy cight different time intervals ca It supports automatic prog suspend/erase-resume comr It has a flag indicating the co Flash security feature for pro Number of program/erase	No Dedicated Number of basic instructions : 136 Instruction bit length : 8 bit Instruction length : 1 to Data bit length : 1, 8 Minimum instruction execution time : 61.4 Interrupt processing time : 0.6 I/O ports (Max) : 4 CMOS I/O : 3 N-ch open drain: 1 Interval time: 0.256 ms to 8.3 s (external cloc Reset generation cycle Main oscillation clock at 10 MHz: 105 ms The sub-CR clock can be used as the sout tcan be used to replace 3 bytes of data. No LIN-UART 2 2 channels 3-bit or 10-bit resolution can be selected. Channel The timer can be configured as an "8-bit till thas the following functions: interval time capture function. Count clock: it can be selected from interrul t can output square wave. 2 channels Interrupt by edge detection (The rising ed It can be used to wake up the device from 1-wire serial control It supports automatic programming (Er suspend/erase-resume commands. It has a flag indicating the completion of tt Flash security feature for protecting the compl	No Yes Number of basic instructions : 136 Instruction bit length : 8 bits Instruction length : 1 to 3 bytes Data bit length : 1 to 3 bytes Data bit length : 1, 8 and 16 b Minimum instruction execution time : 61.5 ns (mach I/O ports (Max) : 4 • I/O p CMOS I/O : 3 • CMC N-ch open drain: 1 • N-ch Interval time: 0.256 ms to 8.3 s (external clock freque Main oscillation clock at 10 MHz: 105 ms (Min) The sub-CR clock can be used as the source clock t can be used to replace 3 bytes of data. No LIN-UART 2 channels B-bit or 10-bit resolution can be selected. 1 Count clock: it can be selected from internal clocks 1 can output square wave. 2 channels 1 Interrupt by edge detection (The rising edge, falling It can be used to wake up the device from standby 1-wire serial control 1 It supports serial writing (asynchronous mode). 1 Eight different time intervals can be selected. 1 It supports automatic programmin	No Dedicated Select Number of basic instructions : 136 Instruction bit length : 8 bits Instruction length : 1 to 3 bytes Data bit length : 1, 8 and 16 bits Minimum instruction execution time : 61.5 ns (machine clock I/O ports (Max) : 4 CMOS I/O : 3 N-ch open drain: • I/O ports (Max) Network (Max) : 4 CMOS I/O : 3 N-ch open drain: • I/O ports (Max) Reset generation cycle Main oscillation clock at 10 MHz: 105 ms (Min) The sub-CR clock can be used as the source clock of the hast t can be used to replace 3 bytes of data. No LIN-UART • Channels B-bit or 10-bit resolution can be selected. I channel • Count clock: it can be selected from internal clocks (seven ty It can output square wave. 2 channels • Interrupt by edge detection (The rising edge, falling edge, or It can be used to wake up the device from standby modes. 1-wire serial control It supports automatic programming (Embedded Algorithm suspend/erase-resume commands. It has a flag indicating the completion of the operation of Em Flash security feat	No Yes Dedicated Selected through sof Number of basic instructions : 136 Instruction length : 8 bits Data bit length : 1 to 3 bytes Deficient : 61.5 ns (machine clock frequency = 16 I/O ports (Max) : 4 • I/O ports (Max) : 5 CMOS I/O : 3 N-ch open drain: 1 • N-ch open drain: 2 Interval time: 0.256 ms to 8.3 s (external clock frequency = 4 MHz) Reset generation cycle Main oscillation clock at 10 MHz: 105 ms (Min) The sub-CR clock can be used as the source clock of the hardware watchd t can bu used to replace 3 bytes of data. No LIN-UART 2 channels Shit or 10-bit resolution can be selected. I channel The timer can be configured as an "8-bit timer tunction, PWC function, PWM fur capture function. Count clock: it can be selected from internal clocks (seven types) and exter <br< td=""></br<>			

FUjitsu

• MB95580H Series

Series									
MB95F582H	MB95F583H	MB95F584H	MB95F582K	MB95F583K	MB95F584K				
		Flash mem	ory product						
supervises the main clock oscillation.									
9 Khyto	10 Kbyto	20 Khyta	9 Khyto	10 Kbyto	20 Kbyte				
o Ruyle	12 KDyte	20 Kbyte	o Ruyle	12 KDyte	20 KDyte				
240 bytes	496 bytes	496 bytes	240 bytes	496 bytes	496 bytes				
		Y	es						
	Na			Vaa					
	INO			res					
	Dedicated		Selec	ted through sof	tware				
 Number of ba 	sic instructions	: 136							
 Instruction bit 	length	: 8 bits							
 Instruction lei 	ngth	: 1 to 3	bytes						
 Data bit lengt 	h	: 1, 8 aı	nd 16 bits						
 Minimum instruction execution time : 61.5 ns (machine clock frequency = 16.25 MHz) 									
 Interrupt proc 	essing time	: 0.6 µs	(machine clock	t frequency = 16	6.25 MHz)				
 I/O ports (Ma 	x) : 12		 I/O ports (Ma 	x):13					
 CMOS I/O 	: 11		 CMOS I/O 	: 11					
 N-ch open drag 	ain: 1		 N-ch open drag 	ain: 2					
Interval time: 0.	256 ms to 8.3 s	(external clock	frequency = 4	MHz)					
 Reset genera 	tion cycle								
Main oscilla	tion clock at 10	MHz: 105 ms (I	Min)						
 The sub-CR of 	clock can be us	ed as the sourc	e clock of the ha	ardware watchd	log timer.				
It can be used t	o replace 3 byt	es of data.							
 A wide range 	of communicat	ion speed can b	e selected by a	dedicated relo	ad timer.				
It has a full duplex double buffer.									
Clock-synchronized serial data transfer and clock-asynchronized serial data transfer is en-									
abled.									
 The LIN funct 	ion can be use	d as a LIN mast	er or a LIN slav	e.					
5 channels									
8-bit or 10-bit re	esolution can be	e selected.							
1 channel									
 The timer car 	be configured	as an "8-bit time	er $ imes$ 2 channels"	or a "16-bit time	$er \times 1$ channel".				
 It has the following the second s	wing functions:	interval timer fu	Inction, PWC fu	nction, PWM fur	nction and input				
capture function.									
Count clock: it can be selected from internal clocks (seven types) and external clocks.									
It can output square wave.									
6 channels									
 Interrupt by e 	dge detection (The rising edge	, falling edge, o	r both edges ca	n be selected.)				
 It can be used 	d to wake up the	e device from st	andby modes.						
 1-wire serial of 									
On-chip debug • It supports serial writing (asynchronous mode).									
	MB95F582H It supervises th 8 Kbyte 240 bytes 240 bytes 40	MB95F582H MB95F583H It supervises the main clock os 8 Kbyte 12 Kbyte 240 bytes 496 bytes 240 bytes 496 bytes No Dedicated Number of basic instructions Instruction length Instruction length Instruction length Minimum instruction execution Interrupt processing time I/O ports (Max) : 12 CMOS I/O : 11 N-ch open drain: 1 Interval time: 0.256 ms to 8.3 s Reset generation cycle Main oscillation clock at 10 The sub-CR clock can be used to replace 3 byte A wide range of communicat It has a full duplex double bu Clock-synchronized serial dat abled. The LIN function can be used Channel The timer can be configured It has the following functions: capture function. Count clock: it can be selected It can output square wave. 6 channels Interrupt by edge detection (10	MB95F582H MB95F583H MB95F583H Flash mem It supervises the main clock oscillation. 8 Kbyte 12 Kbyte 20 Kbyte 240 bytes 496 bytes 496 bytes 240 bytes 496 bytes 496 bytes Yo No Dedicated Number of basic instructions : 136 Instruction bit length : 8 bits Instruction length : 1 to 3 Data bit length : 1, 8 ar Minimum instruction execution time : 61.5 m Interrupt processing time : 0.6 µs !/O ports (Max) : 12 CMOS I/O CMOS I/O : 11 N-ch open drain: 1 Interval time: 0.256 ms to 8.3 s (external clock Reset generation cycle Main oscillation clock at 10 MHz: 105 ms (f The sub-CR clock can be used as the source It can be used to replace 3 bytes of data. A wide range of communication speed can be It has a full duplex double buffer. Clock-synchronized serial data transfer and abled. The LIN function can be used as a LIN mast <td< td=""><td>MB95F582H MB95F583H MB95F584H MB95F582K Flash memory product It supervises the main clock oscillation. 8 Kbyte 12 Kbyte 20 Kbyte 8 Kbyte 240 bytes 496 bytes 496 bytes 240 bytes 240 bytes 496 bytes 496 bytes 240 bytes Yes No Dedicated Select Number of basic instructions : 136 Instruction length : 1 to 3 bytes Data bit length : 1, 8 and 16 bits Minimum instruction execution time : 61.5 ns (machine clock I/O ports (Max) : 12 • I/O ports (Max) Otherval time: 0.256 ms to 8.3 s (external clock frequency = 4 Reset generation cycle Main oscillation clock at 10 MHz: 105 ms (Min) The sub-CR clock can be used as the source clock of the hit 1 has a full duplex double buffer. Clock-synchronized serial data transfer and clock-asynchro abled. 1 The timer can be configured as an "8-bit timer × 2 channels" B-bit or 10-bit resolution can be selected. 1 channels <</td><td>MB95F582H MB95F583H MB95F584H MB95F582K MB95F583K Flash memory product Flash memory product It supervises the main clock oscillation. Flash memory product 8 Kbyte 12 Kbyte 20 Kbyte 8 Kbyte 12 Kbyte 240 bytes 496 bytes 240 bytes 496 bytes 240 bytes 496 bytes 240 bytes 496 bytes 240 bytes 496 bytes 240 bytes 496 bytes Ves Yes Yes Yes Yes Yes No Yes Yes Yes Yes Yes Instruction bit length : 1 to 3 bytes 1.8 and 16 bits Yes Yes Interrupt processing time : 0.6 µs (machine clock frequency = 16 YO ports (Max) : 12 YO ports (Max) : 13 CMOS I/O : 11 YO ports (Max) : 13 Yes Yes</td></td<>	MB95F582H MB95F583H MB95F584H MB95F582K Flash memory product It supervises the main clock oscillation. 8 Kbyte 12 Kbyte 20 Kbyte 8 Kbyte 240 bytes 496 bytes 496 bytes 240 bytes 240 bytes 496 bytes 496 bytes 240 bytes Yes No Dedicated Select Number of basic instructions : 136 Instruction length : 1 to 3 bytes Data bit length : 1, 8 and 16 bits Minimum instruction execution time : 61.5 ns (machine clock I/O ports (Max) : 12 • I/O ports (Max) Otherval time: 0.256 ms to 8.3 s (external clock frequency = 4 Reset generation cycle Main oscillation clock at 10 MHz: 105 ms (Min) The sub-CR clock can be used as the source clock of the hit 1 has a full duplex double buffer. Clock-synchronized serial data transfer and clock-asynchro abled. 1 The timer can be configured as an "8-bit timer × 2 channels" B-bit or 10-bit resolution can be selected. 1 channels <	MB95F582H MB95F583H MB95F584H MB95F582K MB95F583K Flash memory product Flash memory product It supervises the main clock oscillation. Flash memory product 8 Kbyte 12 Kbyte 20 Kbyte 8 Kbyte 12 Kbyte 240 bytes 496 bytes 240 bytes 496 bytes 240 bytes 496 bytes 240 bytes 496 bytes 240 bytes 496 bytes 240 bytes 496 bytes Ves Yes Yes Yes Yes Yes No Yes Yes Yes Yes Yes Instruction bit length : 1 to 3 bytes 1.8 and 16 bits Yes Yes Interrupt processing time : 0.6 µs (machine clock frequency = 16 YO ports (Max) : 12 YO ports (Max) : 13 CMOS I/O : 11 YO ports (Max) : 13 Yes Yes				

(Continued)									
Part number Parameter	MB95F582H	MB95F583H	MB95F5	84H	MB95	6F582K	MB	95F583K	MB95F584K
Watch prescaler	Eight different t	ime intervals ca	an be seleo	cted.					
Flash memory	suspend/eras It has a flag in Flash security Number of	It supports automatic programming (Embedded Algorithm) and program/erase/erase-suspend/erase-resume commands. It has a flag indicating the completion of the operation of Embedded Algorithm. Flash security feature for protecting the content of the Flash memory Number of program/erase cycles 1000 100000 Data retention time 20 years 10 years 5 years							
Standby mode	Sleep mode, st	op mode, watch	n mode, tir	ne-ba	se time	er mode			
Package			F	PT-16	2P-M19 9P-M08 9P-M23				



■ PACKAGES AND CORRESPONDING PRODUCTS

MB95560H Series

Part number Package	MB95F562H	MB95F562K	MB95F563H	MB95F563K	MB95F564H	MB95F564K
LCC-32P-M19	0	0	0	0	0	0
FPT-20P-M09	0	0	0	0	0	0
FPT-20P-M10	0	0	0	0	0	0
FPT-16P-M08	Х	Х	Х	Х	Х	Х
FPT-16P-M23	Х	Х	Х	Х	Х	Х
DIP-8P-M03	Х	Х	Х	Х	Х	Х
FPT-8P-M08	Х	Х	Х	Х	Х	Х

• MB95570H Series

Part number Package	MB95F572H	MB95F572K	MB95F573H	MB95F573K	MB95F574H	MB95F574K
LCC-32P-M19	Х	Х	Х	Х	Х	Х
FPT-20P-M09	Х	Х	Х	Х	Х	Х
FPT-20P-M10	Х	Х	Х	Х	Х	Х
FPT-16P-M08	Х	Х	Х	Х	Х	Х
FPT-16P-M23	Х	Х	Х	Х	Х	Х
DIP-8P-M03	0	0	0	0	0	0
FPT-8P-M08	0	0	0	0	0	0

• MB95580H Series

Part number Package	MB95F582H	MB95F582K	MB95F583H	MB95F583K	MB95F584H	MB95F584K
LCC-32P-M19	0	0	0	0	0	0
FPT-20P-M09	Х	Х	Х	Х	Х	Х
FPT-20P-M10	Х	Х	Х	Х	Х	Х
FPT-16P-M08	0	0	0	0	0	0
FPT-16P-M23	0	0	0	0	0	0
DIP-8P-M03	Х	Х	Х	Х	Х	Х
FPT-8P-M08	Х	Х	Х	Х	Х	Х

O: Available

X: Unavailable

■ DIFFERENCES AMONG PRODUCTS AND NOTES ON PRODUCT SELECTION

• Current consumption

When using the on-chip debug function, take account of the current consumption of Flash program/erase. For details of current consumption, see "■ ELECTRICAL CHARACTERISTICS".

• Package

For details of information on each package, see "■ PACKAGES AND CORRESPONDING PRODUCTS" and "■ PACKAGE DIMENSION".

• Operating voltage

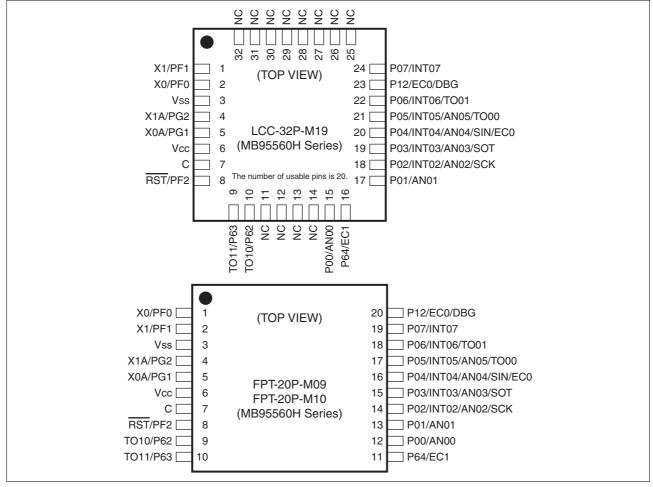
The operating voltage varies, depending on whether the on-chip debug function is used or not. For details of the operating voltage, see "■ ELECTRICAL CHARACTERISTICS".

• On-chip debug function

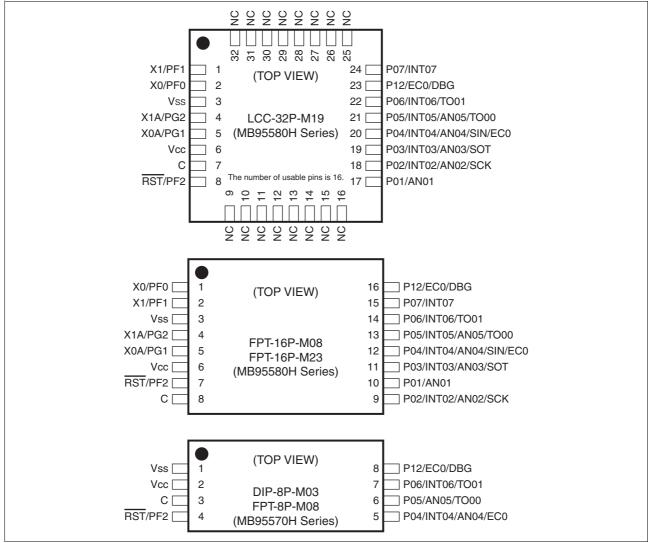
The on-chip debug function requires that V_{CC} , V_{SS} and one serial wire be connected to an evaluation tool. For details of the connection method, refer to "CHAPTER 21 EXAMPLE OF SERIAL PROGRAMMING CONNECTION" in the hardware manual of the MB95560H/570H/580H Series.



■ PIN ASSIGNMENT







■ PIN FUNCTIONS (MB95560H Series, 32 pins)

Pin no.	Pin name	I/O circuit type*	Function			
-	PF1	- В	General-purpose I/O port			
1	X1		Main clock I/O oscillation pin			
2	PF0	B	General-purpose I/O port			
2	X0		Main clock input oscillation pin			
3	Vss	—	Power supply pin (GND)			
4	PG2	с	General-purpose I/O port			
-	X1A	Ŭ	Subclock I/O oscillation pin			
5	PG1	С	General-purpose I/O port			
5	X0A		Subclock input oscillation pin			
6	Vcc	_	Power supply pin			
7	С	_	Decoupling capacitor connection pin			
	PF2		General-purpose I/O port			
8	RST	A	Reset pin Dedicated reset pin on MB95F562H/F563H/F564H			
9	P63	Е	General-purpose I/O port High-current pin			
	TO11		8/16-bit composite timer ch. 1 output pin			
10	P62	Е	General-purpose I/O port High-current pin			
	TO10		8/16-bit composite timer ch. 1 output pin			
11						
12	NC	_	It is an internally connected pin. Always leave it unconnected.			
13	NO		n is an internally connected pin. Always leave it unconnected.			
14						
15	P00	D	General-purpose I/O port High-current pin			
	AN00		A/D converter analog input pin			
16	P64	Е	General-purpose I/O port High-current pin			
	EC1		8/16-bit composite timer ch. 1 clock input pin			
17	P01	D	General-purpose I/O port High-current pin			
	AN01]	A/D converter analog input pin			
	P02		General-purpose I/O port High-current pin			
18	INT02	D	External interrupt input pin			
	AN02	1	A/D converter analog input pin			
	SCK	1	LIN-UART clock I/O pin			

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Pin no.	Pin name	I/O circuit type*	Function
	P03		General-purpose I/O port High-current pin
19	INT03	D	External interrupt input pin
F	AN03		A/D converter analog input pin
	SOT		LIN-UART data output pin
	P04		General-purpose I/O port
	INT04		External interrupt input pin
20	AN04	D	A/D converter analog input pin
	SIN		LIN-UART data input pin
	EC0		8/16-bit composite timer ch. 0 clock input pin
	P05		General-purpose I/O port High-current pin
21	INT05	D	External interrupt input pin
F	AN05		A/D converter analog input pin
	TO00		8/16-bit composite timer ch. 0 output pin
	P06		General-purpose I/O port High-current pin
22	INT06	E	External interrupt input pin
F	TO01		8/16-bit composite timer ch. 0 output pin
	P12		General-purpose I/O port
23	EC0	F	8/16-bit composite timer ch. 0 clock input pin
	DBG		DBG input pin
24	P07	E	General-purpose I/O port High-current pin
	INT07		External interrupt input pin
25			
26			
27			
28	NC		It is an internally connected pin. Always leave it unconnected.
29	NC		n is an internally connected pin. Always leave it unconnected.
30			
31			
32			

*: For the I/O circuit types, see "■ I/O CIRCUIT TYPE".

■ PIN FUNCTIONS (MB95560H Series, 20 pins)

Pin no.	Pin name	I/O circuit type*	Function
	PF0		General-purpose I/O port
1	X0	- В	Main clock input oscillation pin
	PF1		General-purpose I/O port
2	X1	- В	Main clock I/O oscillation pin
3	Vss	—	Power supply pin (GND)
4	PG2	<u> </u>	General-purpose I/O port
4	X1A	- C	Subclock I/O oscillation pin
_	PG1	0	General-purpose I/O port
5	X0A	- C	Subclock input oscillation pin
6	Vcc		Power supply pin
7	С	—	Decoupling capacitor connection pin
	PF2		General-purpose I/O port
8	RST	A	Reset pin Dedicated reset pin on MB95F562H/F563H/F564H
9	P62	Е	General-purpose I/O port High-current pin
	TO10		8/16-bit composite timer ch. 1 output pin
10	P63	Е	General-purpose I/O port High-current pin
	TO11		8/16-bit composite timer ch. 1 output pin
11	P64	E	General-purpose I/O port High-current pin
	EC1		8/16-bit composite timer ch. 1 clock input pin
12	P00	D	General-purpose I/O port High-current pin
	AN00		A/D converter analog input pin
13	P01	D	General-purpose I/O port High-current pin
	AN01		A/D converter analog input pin
	P02		General-purpose I/O port High-current pin
14	INT02	D	External interrupt input pin
	AN02		A/D converter analog input pin
	SCK		LIN-UART clock I/O pin
	P03		General-purpose I/O port High-current pin
15	INT03	D	External interrupt input pin
	AN03		A/D converter analog input pin
	SOT		LIN-UART data output pin

(Continued)

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Pin no.	Pin name	I/O circuit type*	Function
	P04		General-purpose I/O port
	INT04		External interrupt input pin
16	AN04	D	A/D converter analog input pin
	SIN		LIN-UART data input pin
	EC0		8/16-bit composite timer ch. 0 clock input pin
	P05		General-purpose I/O port High-current pin
17	INT05	D	External interrupt input pin
	AN05		A/D converter analog input pin
	TO00		8/16-bit composite timer ch. 0 output pin
10	P06	_	General-purpose I/O port High-current pin
18	INT06	E	External interrupt input pin
	TO01		8/16-bit composite timer ch. 0 output pin
19	P07	E	General-purpose I/O port High-current pin
	INT07		External interrupt input pin
	P12		General-purpose I/O port
20	EC0	F	8/16-bit composite timer ch. 0 clock input pin
	DBG		DBG input pin

*: For the I/O circuit types, see "■ I/O CIRCUIT TYPE".

■ PIN FUNCTIONS (MB95570H Series, 8 pins)

Pin no.	Pin name	I/O circuit type*	Function
1	Vss	_	Power supply pin (GND)
2	Vcc	—	Power supply pin
3	С	—	Decoupling capacitor connection pin
	PF2		General-purpose I/O port
4	RST	A	Reset pin Dedicated reset pin on MB95F572H/F573H/F574H
	P04		General-purpose I/O port
5	INT04	D	External interrupt input pin
5	AN04		A/D converter analog input pin
	EC0		8/16-bit composite timer ch. 0 clock input pin
	P05		General-purpose I/O port High-current pin
6	AN05	D	A/D converter analog input pin
	TO00		8/16-bit composite timer ch. 0 output pin
_	P06		General-purpose I/O port High-current pin
7	INT06	E	External interrupt input pin
l T	TO01]	8/16-bit composite timer ch. 0 output pin
	P12		General-purpose I/O port
8	EC0	F	8/16-bit composite timer ch. 0 clock input pin
	DBG		DBG input pin

*: For the I/O circuit types, see "■ I/O CIRCUIT TYPE".

■ PIN FUNCTIONS (MB95580H Series, 32 pins)

Pin no.	Pin name	I/O circuit type*	Function					
4	PF1	В	General-purpose I/O port					
1 -	X1		Main clock I/O oscillation pin					
0	PF0	- В	General-purpose I/O port					
2	X0		Main clock input oscillation pin Power supply pin (GND)					
3	Vss	—	Power supply pin (GND)					
4	PG2	с	General-purpose I/O port					
4	X1A		Subclock I/O oscillation pin					
5	PG1	с	General-purpose I/O port					
5	X0A		Subclock input oscillation pin					
6	Vcc	—	Power supply pin					
7	С	—	Decoupling capacitor connection pin					
	PF2		General-purpose I/O port					
8	RST	A	Reset pin Dedicated reset pin on MB95F582H/F583H/F584H					
9								
10	NC		It is an internally connected pin. Always leave it unconnected.					
11								
12								
13								
14								
15								
16								
17	P01	D	General-purpose I/O port High-current pin					
	AN01		A/D converter analog input pin					
	P02		General-purpose I/O port High-current pin					
18	INT02	D	External interrupt input pin					
	AN02		A/D converter analog input pin					
	SCK		LIN-UART clock I/O pin					
	P03		General-purpose I/O port High-current pin					
19	INT03	D	External interrupt input pin					
	AN03		A/D converter analog input pin					
	SOT		LIN-UART data output pin					

(Continued)

(Continued)

Pin no.	Pin name	I/O circuit type*	Function
	P04		General-purpose I/O port
	INT04		External interrupt input pin
20	AN04	D	A/D converter analog input pin
	SIN		LIN-UART data input pin
	EC0		8/16-bit composite timer ch. 0 clock input pin
	P05		General-purpose I/O port High-current pin
21	INT05	D	External interrupt input pin
	AN05		A/D converter analog input pin
	TO00		8/16-bit composite timer ch. 0 output pin
	P06		General-purpose I/O port High-current pin
22	INT06	E	External interrupt input pin
	TO01		8/16-bit composite timer ch. 0 output pin
	P12		General-purpose I/O port
23	EC0	F	8/16-bit composite timer ch. 0 clock input pin
	DBG		DBG input pin
24	P07	E	General-purpose I/O port High-current pin
	INT07		External interrupt input pin
25			
26			
27			
28	NC		It is an internally connected pin. Always leave it unconnected.
29	NC		n is an internally connected pin. Always leave it unconnected.
30			
31			
32			

*: For the I/O circuit types, see "■ I/O CIRCUIT TYPE".

■ PIN FUNCTIONS (MB95580H Series, 16 pins)

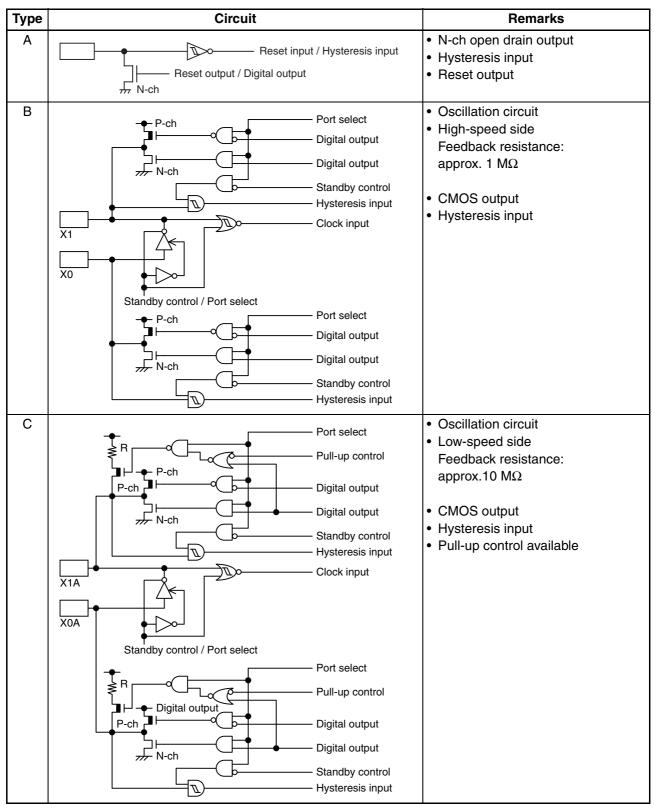
Pin no.	Pin name	I/O circuit type*	Function
4	PF0	В	General-purpose I/O port
1 -	X0		Main clock input oscillation pin
2	PF1	В	General-purpose I/O port
2	X1		Main clock I/O oscillation pin
3	Vss	_	Power supply pin (GND)
4	PG2	с	General-purpose I/O port
4	X1A		Subclock I/O oscillation pin
5	PG1	с	General-purpose I/O port
5	X0A		Subclock input oscillation pin
6	Vcc	—	Power supply pin
	PF2		General-purpose I/O port
7	RST	A	Reset pin Dedicated reset pin on MB95F582H/F583H/F584H
8	С	_	Decoupling capacitor connection pin
	P02		General-purpose I/O port High-current pin
9	INT02	D	External interrupt input pin
l t	AN02		A/D converter analog input pin
	SCK		LIN-UART clock I/O pin
10	P01	D	General-purpose I/O port High-current pin
Ī	AN01		A/D converter analog input pin
	P03		General-purpose I/O port High-current pin
11	INT03	D	External interrupt input pin
	AN03		A/D converter analog input pin
[SOT		LIN-UART data output pin
	P04		General-purpose I/O port
[INT04		External interrupt input pin
12	AN04	D	A/D converter analog input pin
[SIN		LIN-UART data input pin
Ī	EC0		8/16-bit composite timer ch. 0 clock input pin

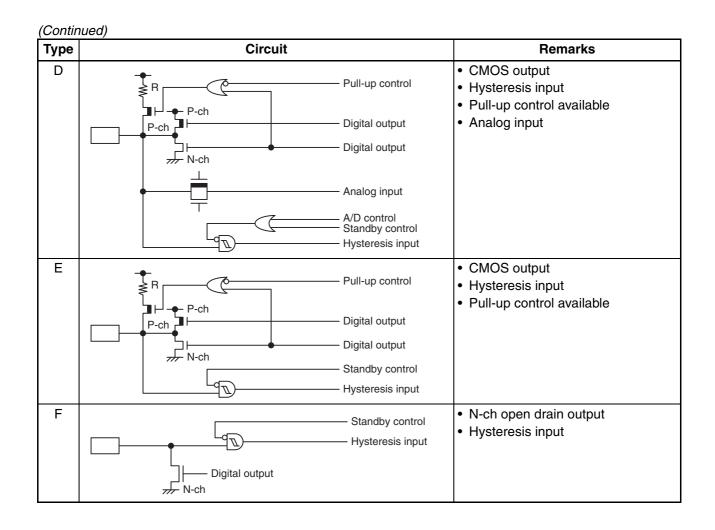
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Pin no.	Pin name	I/O circuit type*	Function
	P05		General-purpose I/O port High-current pin
13	INT05	D	External interrupt input pin
	AN05		A/D converter analog input pin
	TO00		8/16-bit composite timer ch. 0 output pin
	P06	_	General-purpose I/O port High-current pin
14	INT06	E	External interrupt input pin
	TO01		8/16-bit composite timer ch. 0 output pin
15	P07	E	General-purpose I/O port High-current pin
	INT07		External interrupt input pin
16	P12		General-purpose I/O port
	EC0	F	8/16-bit composite timer ch. 0 clock input pin
	DBG		DBG input pin

*: For the I/O circuit types, see "■ I/O CIRCUIT TYPE".

■ I/O CIRCUIT TYPE





NOTES ON DEVICE HANDLING

· Preventing latch-ups

When using the device, ensure that the voltage applied does not exceed the maximum voltage rating. In a CMOS IC, if a voltage higher than V_{CC} or a voltage lower than V_{SS} is applied to an input/output pin that is neither a medium-withstand voltage pin nor a high-withstand voltage pin, or if a voltage out of the rating range of power supply voltage mentioned in "1. Absolute Maximum Ratings" of "■ ELECTRICAL CHARACTERISTICS" is applied to the V_{CC} pin or the V_{SS} pin, a latch-up may occur.

When a latch-up occurs, power supply current increases significantly, which may cause a component to be thermally destroyed.

Stabilizing supply voltage

Supply voltage must be stabilized.

A malfunction may occur when power supply voltage fluctuates rapidly even though the fluctuation is within the guaranteed operating range of the Vcc power supply voltage.

As a rule of voltage stabilization, suppress voltage fluctuation so that the fluctuation in V_{cc} ripple (p-p value) at the commercial frequency (50 Hz/60 Hz) does not exceed 10% of the standard V_{cc} value, and the transient fluctuation rate does not exceed 0.1 V/ms at a momentary fluctuation such as switching the power supply.

• Notes on using the external clock

When an external clock is used, oscillation stabilization wait time is required for power-on reset, wake-up from subclock mode or stop mode.

■ PIN CONNECTION

• Treatment of unused pins

If an unused input pin is left unconnected, a component may be permanently damaged due to malfunctions or latch-ups. Always pull up or pull down an unused input pin through a resistor of at least 2 k Ω . Set an unused input/output pin to the output state and leave it unconnected, or set it to the input state and treat it the same as an unused input pin. If there is an unused output pin, leave it unconnected.

• Power supply pins

To reduce unnecessary electro-magnetic emission, prevent malfunctions of strobe signals due to an increase in the ground level, and conform to the total output current standard, always connect the V_{cc} pin and the V_{ss} pin to the power supply and ground outside the device. In addition, connect the current supply source to the V_{cc} pin and the V_{ss} pin with low impedance.

It is also advisable to connect a ceramic capacitor of approximately 0.1 μ F as a bypass capacitor between the V_{cc} pin and the V_{ss} pin at a location close to this device.

DBG pin

Connect the DBG pin directly to an external pull-up resistor.

To prevent the device from unintentionally entering the debug mode due to noise, minimize the distance between the DBG pin and the Vcc or Vss pin when designing the layout of the printed circuit board. The DBG pin should not stay at "L" level after power-on until the reset output is released.

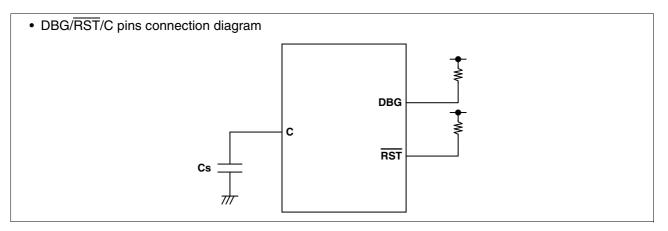
RST pin

Connect the RST pin directly to an external pull-up resistor.

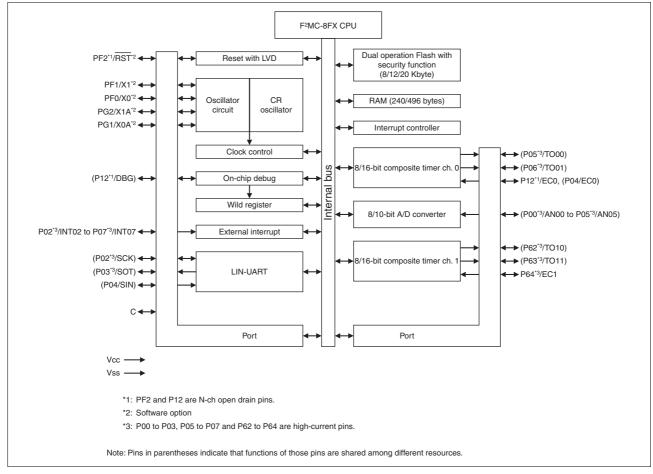
To prevent the device from unintentionally entering the reset mode due to noise, minimize the distance between the RST pin and the Vcc or Vss pin when designing the layout of the printed circuit board. The PF2/RST pin functions as the reset input/output pin after power-on. In addition, the reset output of the PF2/RST pin can be enabled by the RSTOE bit in the SYSC register, and the reset input function and the general purpose I/O function can be selected by the RSTEN bit in the SYSC register.

• C pin

Use a ceramic capacitor or a capacitor with equivalent frequency characteristics. The bypass capacitor for the V_{CC} pin must have a capacitance larger than C_S. For the connection to a decoupling capacitor C_S, see the diagram below. To prevent the device from unintentionally entering a mode to which the device is not set to transit due to noise, minimize the distance between the C pin and C_S and the distance between C_S and the V_{SS} pin when designing the layout of a printed circuit board.

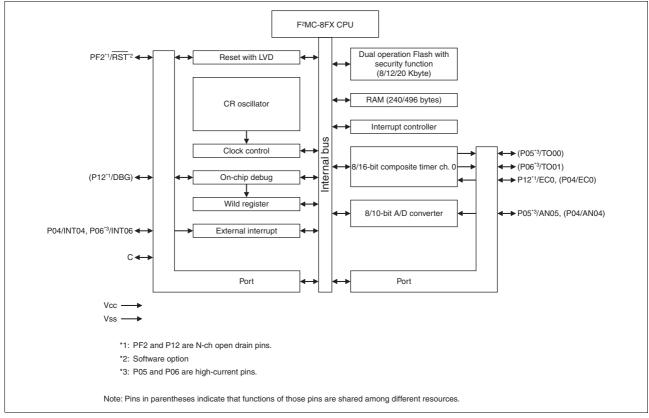


■ BLOCK DIAGRAM (MB95560H Series)

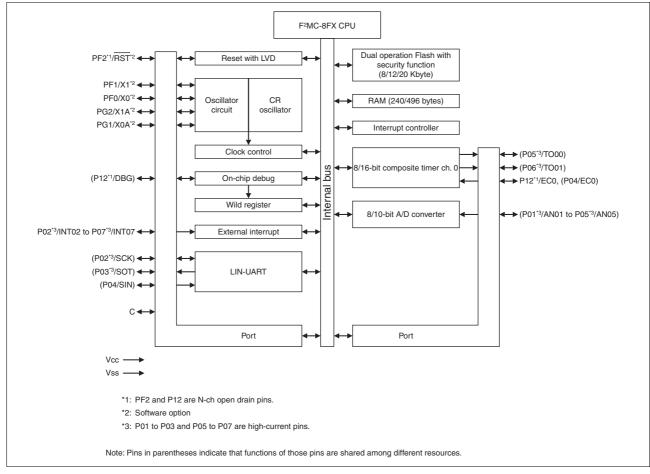




■ BLOCK DIAGRAM (MB95570H Series)



■ BLOCK DIAGRAM (MB95580H Series)



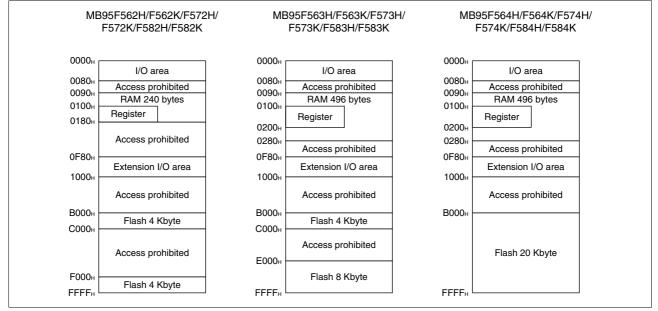


■ CPU CORE

• Memory space

The memory space of the MB95560H/570H/580H Series is 64 Kbyte in size, and consists of an I/O area, a data area, and a program area. The memory space includes areas intended for specific purposes such as general-purpose registers and a vector table. The memory maps of the MB95560H/570H/580H Series are shown below.

• Memory maps



■ I/O MAP (MB95560H Series)

Address	Register abbreviation	Register name	R/W	Initial value
0000н	PDR0	Port 0 data register	R/W	0000000в
0001н	DDR0	Port 0 direction register	R/W	0000000в
0002н	PDR1	Port 1 data register	R/W	0000000в
0003н	DDR1	Port 1 direction register	R/W	0000000в
0004н		(Disabled)		_
0005н	WATR	Oscillation stabilization wait time setting register	R/W	11111111в
0006н	PLLC	PLL control register	R/W	000Х0000в
0007н	SYCC	System clock control register	R/W	XXX11011 _B
0008н	STBC	Standby control register	R/W	00000000в
0009н	RSRR	Reset source register	R/W	000XXXXX _B
000Ан	TBTC	Time-base timer control register	R/W	0000000в
000Вн	WPCR	Watch prescaler control register	R/W	0000000в
000Сн	WDTC	Watchdog timer control register	R/W	00XX0000 _B
000Dн	SYCC2	System clock control register 2	R/W	XXXX0011в
000Eн	STBC2	Standby control register 2	R/W	0000000в
000Fн to 0015н	_	(Disabled)	_	
0016 н	PDR6	Port 6 data register	R/W	0000000в
0017 н	DDR6	Port 6 direction register	R/W	0000000в
0018н to 0027н		(Disabled)	_	_
0028н	PDRF	Port F data register	R/W	0000000в
0029н	DDRF	Port F direction register	R/W	0000000в
002А н	PDRG	Port G data register	R/W	0000000в
002Вн	DDRG	Port G direction register	R/W	0000000в
002Сн	PUL0	Port 0 pull-up register	R/W	00000000В
002Dн to 0032н		(Disabled)	_	_
0033н	PUL6	Port 6 pull-up register	R/W	0000000в
0034н	—	(Disabled)	—	_
0035н	PULG	Port G pull-up register	R/W	0000000в
0036н	T01CR1	8/16-bit composite timer 01 status control register 1	R/W	0000000в
0037н	T00CR1	8/16-bit composite timer 00 status control register 1	R/W	0000000в
0038н	T11CR1	8/16-bit composite timer 11 status control register 1	R/W	0000000в
0039н	T10CR1	8/16-bit composite timer 10 status control register 1	R/W	0000000в
003Ан to 0048н		(Disabled)	_	

Address	Register abbreviation	Register name	R/W	Initial value
0049н	EIC10	External interrupt circuit control register ch. 2/ch. 3	R/W	00000000в
004Aн	EIC20	External interrupt circuit control register ch. 4/ch. 5	R/W	0000000в
004Bн	EIC30	External interrupt circuit control register ch. 6/ch. 7	R/W	0000000в
004Сн, 004Dн	_	(Disabled)	_	
004Eн	LVDR	LVDR reset voltage selection ID register	R/W	0000000в
004Fн		(Disabled)	—	_
0050н	SCR	LIN-UART serial control register	R/W	0000000в
0051 н	SMR	LIN-UART serial mode register	R/W	0000000в
0052н	SSR	LIN-UART serial status register	R/W	00001000в
0050	RDR	LIN-UART receive data register	R/W	0000000в
0053н	TDR	LIN-UART transmit data register	R/W	0000000в
0054н	ESCR	LIN-UART extended status control register	R/W	00000100в
0055н	ECCR	LIN-UART extended communication control register	R/W	000000XX _B
0056н to 006Вн	_	(Disabled)	_	_
006Сн	ADC1	8/10-bit A/D converter control register 1	R/W	0000000в
006Dн	ADC2	8/10-bit A/D converter control register 2	R/W	0000000в
006Е н	ADDH	8/10-bit A/D converter data register (upper)	R/W	0000000в
006Fн	ADDL	8/10-bit A/D converter data register (lower)	R/W	0000000в
0070н		(Disabled)		_
0071 н	FSR2	Flash memory status register 2	R/W	0000000в
0072н	FSR	Flash memory status register	R/W	000Х0000в
0073н	SWRE0	Flash memory sector write control register 0	R/W	0000000в
0074н	FSR3	Flash memory status register 3	R	000XXXXXB
0075н	FSR4	Flash memory status register 4	R/W	0000000в
0076н	WREN	Wild register address compare enable register	R/W	0000000в
0077н	WROR	Wild register data test setting register	R/W	0000000в
0078н		Mirror of register bank pointer (RP) and direct bank pointer (DP)	_	_
0079 н	ILR0	Interrupt level setting register 0	R/W	11111111в
007Ан	ILR1	Interrupt level setting register 1	R/W	11111111в
007Вн	ILR2	Interrupt level setting register 2	R/W	11111111в
007Сн	ILR3	Interrupt level setting register 3	R/W	11111111в
007Dн	ILR4	Interrupt level setting register 4	R/W	11111111в
007Е н	ILR5	Interrupt level setting register 5	R/W	11111111в
007Fн	_	(Disabled)	-	
0F80н	WRARH0	Wild register address setting register (upper) ch. 0	R/W	0000000в
0F81н	WRARL0	Wild register address setting register (lower) ch. 0	R/W	0000000в
0F82н	WRDR0	Wild register data setting register ch. 0	R/W	0000000в
			1	(Continued)



Address	Register abbreviation	Register name	R/W	Initial value
0F83н	WRARH1	Wild register address setting register (upper) ch. 1	R/W	0000000в
0F84н	WRARL1	Wild register address setting register (lower) ch. 1	R/W	0000000в
0F85н	WRDR1	Wild register data setting register ch. 1	R/W	0000000в
0F86н	WRARH2	Wild register address setting register (upper) ch. 2	R/W	0000000в
0F87н	WRARL2	Wild register address setting register (lower) ch. 2	R/W	0000000в
0F88⊦	WRDR2	Wild register data setting register ch. 2	R/W	00000000в
0F89н to 0F91н	_	(Disabled)	_	_
0F92н	T01CR0	8/16-bit composite timer 01 status control register 0	R/W	0000000в
0F93н	T00CR0	8/16-bit composite timer 00 status control register 0	R/W	0000000в
0F94н	T01DR	8/16-bit composite timer 01 data register	R/W	0000000в
0F95н	T00DR	8/16-bit composite timer 00 data register	R/W	0000000в
0F96н	TMCR0	8/16-bit composite timer 00/01 timer mode control register	R/W	0000000в
0F97н	T11CR0	8/16-bit composite timer 11 status control register 0	R/W	0000000в
0F98н	T10CR0	8/16-bit composite timer 10 status control register 0	R/W	0000000в
0F99н	T11DR	8/16-bit composite timer 11 data register	R/W	0000000в
0F9А н	T10DR	8/16-bit composite timer 10 data register	R/W	0000000в
0F9Bн	TMCR1	8/16-bit composite timer 10/11 timer mode control register	R/W	0000000в
0F9C⊦ to 0FBB⊦	_	(Disabled)	_	_
0FBCH	BGR1	LIN-UART baud rate generator register 1	R/W	0000000в
0FBDH	BGR0	LIN-UART baud rate generator register 0	R/W	0000000в
0FBEн to 0FC2н	_	(Disabled)	_	
0FC3н	AIDRL	A/D input disable register (lower)	R/W	0000000в
0FC4н to 0FE3н	_	(Disabled)	_	
0FE4н	CRTH	Main CR clock trimming register (upper)	R/W	000XXXXX _B
0FE5н	CRTL	Main CR clock trimming register (lower)	R/W	000XXXXX _B
0FE6⊦	—	(Disabled)	_	_
0FE7н	CRTDA	Main CR clock temperature dependent adjustment register	R/W	000XXXXX _B
0FE8⊦	SYSC	System configuration register	R/W	11000011в
0FE9⊦	CMCR	Clock monitoring control register	R/W	00000000в
0FEAH	CMDR	Clock monitoring data register	R/W	0000000в

(Continued)

(Continued)

Address	Register abbreviation	Register name	R/W	Initial value
0FEBн	WDTH	Watchdog timer selection ID register (upper)	R	$\mathbf{X}\mathbf{X}\mathbf{X}\mathbf{X}\mathbf{X}\mathbf{X}\mathbf{X}_{B}$
0FECH	WDTL	Watchdog timer selection ID register (lower)	R	XXXXXXXXB
0FED⊦ to 0FFF⊦	_	(Disabled)	_	_

• R/W access symbols

- R/W : Readable / Writable
- R : Read only

• Initial value symbols

- 0 : The initial value of this bit is "0".
- 1 : The initial value of this bit is "1".
- X : The initial value of this bit is undefined.
- Note: Do not write to an address that is "(Disabled)". If a "(Disabled)" address is read, an indeterminate value is returned.

FUJITSU

■ I/O MAP (MB95570H Series)

	i			
Address	Register abbreviation	Register name	R/W	Initial value
0000н	PDR0	Port 0 data register	R/W	0000000в
0001 н	DDR0	Port 0 direction register	R/W	0000000в
0002н	PDR1	Port 1 data register	R/W	0000000в
0003н	DDR1	Port 1 direction register	R/W	0000000в
0004н	—	(Disabled)	_	_
0005н	WATR	Oscillation stabilization wait time setting register	R/W	11111111 в
0006н	PLLC	PLL control register	R/W	000Х000в
0007н	SYCC	System clock control register	R/W	XXX11011в
0008н	STBC	Standby control register	R/W	0000000в
0009н	RSRR	Reset source register	R/W	000XXXXXB
000Ан	TBTC	Time-base timer control register	R/W	0000000в
000Вн	WPCR	Watch prescaler control register	R/W	0000000в
000Сн	WDTC	Watchdog timer control register	R/W	00XX0000 _B
000Dн	SYCC2	System clock control register 2	R/W	XXXX0011 _B
000Eн	STBC2	Standby control register 2	R/W	0000000в
000Fн				
to 0027н	_	(Disabled)	-	—
0028н	PDRF	Port F data register	R/W	0000000в
0029н	DDRF	Port F direction register	R/W	0000000в
002Ан, 002Вн	—	(Disabled)	_	
002Сн	PUL0	Port 0 pull-up register	R/W	0000000в
002Dн to 0035н	_	(Disabled)	_	
0036н	T01CR1	8/16-bit composite timer 01 status control register 1	R/W	0000000в
0037н	T00CR1	8/16-bit composite timer 00 status control register 1	R/W	0000000в
0038н to 0049н	_	(Disabled)		
004Ан	EIC20	External interrupt circuit control register ch. 4	R/W	0000000в
004Вн	EIC30	External interrupt circuit control register ch. 6	R/W	0000000в
004Сн, 004Dн	—	(Disabled)	_	
004Eн	LVDR	LVDR reset voltage selection ID register	R/W	0000000в
004Fн to 006Bн	_	(Disabled)		

	Register abbreviation	Register name	R/W	Initial value
006Сн	ADC1	8/10-bit A/D converter control register 1	R/W	0000000в
006Dн	ADC2	8/10-bit A/D converter control register 2	R/W	0000000в
006Eн	ADDH	8/10-bit A/D converter data register (upper)	R/W	0000000в
006Fн	ADDL	8/10-bit A/D converter data register (lower)	R/W	0000000в
0070н		(Disabled)	—	_
0071 н	FSR2	Flash memory status register 2	R/W	0000000в
0072н	FSR	Flash memory status register	R/W	000X0000B
0073н	SWRE0	Flash memory sector write control register 0	R/W	0000000в
0074н	FSR3	Flash memory status register 3	R	000XXXXX _B
0075н	FSR4	Flash memory status register 4	R/W	0000000в
0076н	WREN	Wild register address compare enable register	R/W	0000000в
0077н	WROR	Wild register data test setting register	R/W	0000000в
0078 н		Mirror of register bank pointer (RP) and direct bank pointer (DP)	_	_
0079 н	ILR0	Interrupt level setting register 0	R/W	11111111
007Ан	ILR1	Interrupt level setting register 1	R/W	11111111
007Вн, 007Сн		(Disabled)	—	_
007Dн	ILR4	Interrupt level setting register 4	R/W	11111111
007Е н	ILR5	Interrupt level setting register 5	R/W	11111111в
007Fн		(Disabled)	_	_
0F80н	WRARH0	Wild register address setting register (upper) ch. 0	R/W	0000000в
0F81н	WRARL0	Wild register address setting register (lower) ch. 0	R/W	0000000в
0F82н	WRDR0	Wild register data setting register ch. 0	R/W	0000000в
0F83н	WRARH1	Wild register address setting register (upper) ch. 1	R/W	0000000в
0F84н	WRARL1	Wild register address setting register (lower) ch. 1	R/W	0000000в
0F85н	WRDR1	Wild register data setting register ch. 1	R/W	0000000в
0F86н	WRARH2	Wild register address setting register (upper) ch. 2	R/W	0000000в
0F87н	WRARL2	Wild register address setting register (lower) ch. 2	R/W	0000000в
0F88н	WRDR2	Wild register data setting register ch. 2	R/W	0000000в
0F89⊦ to 0F91⊦		(Disabled)	_	_
0 F 92н	T01CR0	8/16-bit composite timer 01 status control register 0	R/W	0000000в
0F93н	T00CR0	8/16-bit composite timer 00 status control register 0	R/W	0000000в
0F94н	T01DR	8/16-bit composite timer 01 data register	R/W	0000000в
0F95н	T00DR	8/16-bit composite timer 00 data register	R/W	0000000в
0F96н	TMCR0	8/16-bit composite timer 00/01 timer mode control register	R/W	0000000в
0F97⊦ to		(Disabled)	_	



(Continued)

Address	Register abbreviation	Register name	R/W	Initial value
0FC3н	AIDRL	A/D input disable register (lower)	R/W	0000000в
0FC4н to 0FE3н	_	(Disabled)	_	_
0FE4н	CRTH	Main CR clock trimming register (upper)	R/W	000XXXXX _B
0FE5н	CRTL	Main CR clock trimming register (lower)	R/W	000XXXXX _B
0FE6н	—	(Disabled)	—	—
0FE7н	CRTDA	Main CR clock temperature dependent adjustment register	R/W	000XXXXX _B
0FE8н	SYSC	System configuration register	R/W	11000011в
0FE9н	CMCR	Clock monitoring control register	R/W	0000000в
0FEAH	CMDR	Clock monitoring data register	R/W	0000000в
0FEBH	WDTH	Watchdog timer selection ID register (upper)	R/W	XXXXXXXXB
0FECH	WDTL	Watchdog timer selection ID register (lower)	R/W	XXXXXXXXB
0FED⊦ to 0FFF⊦	_	(Disabled)	_	_

- R/W access symbols
 - R/W : Readable / Writable
 - R : Read only

• Initial value symbols

- 0 : The initial value of this bit is "0".
- 1 : The initial value of this bit is "1".
- X : The initial value of this bit is undefined.
- Note: Do not write to an address that is "(Disabled)". If a "(Disabled)" address is read, an indeterminate value is returned.

■ I/O MAP (MB95580H Series)

Address	Register abbreviation	Register name	R/W	Initial value
0000н	PDR0	Port 0 data register	R/W	0000000в
0001 н	DDR0	Port 0 direction register	R/W	0000000в
0002н	PDR1	Port 1 data register	R/W	0000000в
0003н	DDR1	Port 1 direction register	R/W	0000000в
0004н		(Disabled)	_	
0005н	WATR	Oscillation stabilization wait time setting register	R/W	11111111 _В
0006н	PLLC	PLL control register	R/W	000Х000в
0007н	SYCC	System clock control register	R/W	XXX11011в
0008н	STBC	Standby control register	R/W	0000000в
0009н	RSRR	Reset source register	R/W	000XXXXXB
000Ан	TBTC	Time-base timer control register	R/W	0000000в
000Вн	WPCR	Watch prescaler control register	R/W	0000000в
000Сн	WDTC	Watchdog timer control register	R/W	00XX0000 _B
000Dн	SYCC2	System clock control register 2	R/W	XXXX0011 в
000EH	STBC2	Standby control register 2	R/W	0000000в
000Fн to 0027н	_	(Disabled)	_	_
0028н	PDRF	Port F data register	R/W	0000000в
0029н	DDRF	Port F direction register	R/W	0000000в
002Ан	PDRG	Port G data register	R/W	0000000в
002Вн	DDRG	Port G direction register	R/W	0000000в
002Сн	PUL0	Port 0 pull-up register	R/W	0000000в
002Dн to 0034н	_	(Disabled)	_	_
0035н	PULG	Port G pull-up register	R/W	0000000в
0036н	T01CR1	8/16-bit composite timer 01 status control register 1	R/W	0000000в
0037н	T00CR1	8/16-bit composite timer 00 status control register 1	R/W	0000000в
0038н to 0048н		(Disabled)	_	_
0049н	EIC10	External interrupt circuit control register ch. 2/ch. 3	R/W	0000000в
004Ан	EIC20	External interrupt circuit control register ch. 4/ch. 5	R/W	0000000в
004Вн	EIC30	External interrupt circuit control register ch. 6/ch. 7	R/W	0000000в
004Сн, 004Dн	—	(Disabled)		
004Eн	LVDR	LVDR reset voltage selection ID register	R/W	0000000в
004F н		(Disabled)	_	



Address	Register abbreviation	Register name	R/W	Initial value
0050н	SCR	LIN-UART serial control register	R/W	0000000в
0051 н	SMR	LIN-UART serial mode register	R/W	0000000в
0052н	SSR	LIN-UART serial status register	R/W	00001000в
0050	RDR	LIN-UART receive data register	R/W	0000000в
0053н	TDR	LIN-UART transmit data register	R/W	0000000в
0054н	ESCR	LIN-UART extended status control register	R/W	00000100в
0055н	ECCR	LIN-UART extended communication control register	R/W	000000XXB
0056н to 006Вн	_	(Disabled)	_	_
006Сн	ADC1	8/10-bit A/D converter control register 1	R/W	0000000в
006Dн	ADC2	8/10-bit A/D converter control register 2	R/W	0000000в
006Eн	ADDH	8/10-bit A/D converter data register (upper)	R/W	0000000в
006F н	ADDL	8/10-bit A/D converter data register (lower)	R/W	0000000в
0070н		(Disabled)	_	
0071 н	FSR2	Flash memory status register 2	R/W	0000000в
0072н	FSR	Flash memory status register	R/W	000X0000 _B
0073н	SWRE0	Flash memory sector write control register 0	R/W	0000000в
0074н	FSR3	Flash memory status register 3	R	000XXXXXB
0075н	FSR4	Flash memory status register 4	R/W	0000000в
0076н	WREN	Wild register address compare enable register	R/W	0000000в
0077н	WROR	Wild register data test setting register	R/W	0000000в
0078 н		Mirror of register bank pointer (RP) and direct bank pointer (DP)	—	_
0079н	ILR0	Interrupt level setting register 0	R/W	11111111
007А н	ILR1	Interrupt level setting register 1	R/W	11111111в
007Вн	ILR2	Interrupt level setting register 2	R/W	11111111
007Сн	_	(Disabled)	—	
007Dн	ILR4	Interrupt level setting register 4	R/W	11111111
007Ен	ILR5	Interrupt level setting register 5	R/W	11111111
007F н	_	(Disabled)		_
0F80н	WRARH0	Wild register address setting register (upper) ch. 0	R/W	0000000в
0F81н	WRARL0	Wild register address setting register (lower) ch. 0	R/W	0000000в
0F82н	WRDR0	Wild register data setting register ch. 0	R/W	0000000в
0F83н	WRARH1	Wild register address setting register (upper) ch. 1	R/W	0000000в
0F84н	WRARL1	Wild register address setting register (lower) ch. 1	R/W	0000000в
0F85н	WRDR1	Wild register data setting register ch. 1	R/W	0000000в
0F86н	WRARH2	Wild register address setting register (upper) ch. 2	R/W	0000000в
0F87н	WRARL2	Wild register address setting register (lower) ch. 2	R/W	0000000в
0F88⊦	WRDR2	Wild register data setting register ch. 2	R/W	0000000в

(Continued)

Address	Register abbreviation	Register name	R/W	Initial value
0F89н				
to 0F91⊦	—	(Disabled)	_	—
0Г91н 0F92н	T01CR0	8/16-bit composite timer 01 status control register 0	R/W	0000000в
0Г92н 0F93н	T00CR0	8/16-bit composite timer 00 status control register 0	R/W	00000000в
0F94н	T01DR	8/16-bit composite timer 01 data register	R/W	00000000в
0F95н	T00DR	8/16-bit composite timer 00 data register	R/W	0000000в
0F96н	TMCR0	8/16-bit composite timer 00/01 timer mode control register	R/W	00000000в
0F97н				
to 0FBBн	_	(Disabled)	—	_
0FBCH	BGR1	LIN-UART baud rate generator register 1	R/W	0000000в
0FBDH	BGR0	LIN-UART baud rate generator register 0	R/W	0000000в
0FBEн to 0FC2н		(Disabled)	_	_
0FC3н	AIDRL	A/D input disable register (lower)	R/W	0000000в
0FC4н to 0FE3н	_	(Disabled)	_	
0FE4н	CRTH	Main CR clock trimming register (upper)	R/W	000XXXXXB
0FE5H	CRTL	Main CR clock trimming register (lower)	R/W	000XXXXXB
0FE6н		(Disabled)	_	—
0FE7н	CRTDA	Main CR clock temperature dependent adjustment	R/W	000XXXXXB
0FE8⊦	SYSC	System configuration register	R/W	11000011в
0FE9н	CMCR	Clock monitoring control register	R/W	0000000в
0FEAн	CMDR	Clock monitoring data register	R/W	0000000в
0FEBн	WDTH	Watchdog timer selection ID register (upper)	R/W	XXXXXXXX
0FECH	WDTL	Watchdog timer selection ID register (lower)	R/W	XXXXXXXX
0FED⊦ to 0FFF⊦	_	(Disabled)	_	_

• R/W access symbols

R/W : Readable / Writable

R : Read only

Initial value symbols

- 0 : The initial value of this bit is "0".
- 1 : The initial value of this bit is "1".
- X : The initial value of this bit is undefined.
- Note: Do not write to an address that is "(Disabled)". If a "(Disabled)" address is read, an indeterminate value is returned.

■ INTERRUPT SOURCE TABLE (MB95560H Series)

		Vector tab	le address		Priority order of
Interrupt source	Interrupt request number	Upper	Lower	Bit name of interrupt level setting register	interrupt sources of the same level (occurring simultaneously)
External interrupt ch. 4	IRQ00	FFFA H	FFFB⊦	L00 [1:0]	High
External interrupt ch. 5	IRQ01	FFF8H	FFF9⊦	L01 [1:0]	▲
External interrupt ch. 2	IRQ02	FFF6H	FFF7H	L02 [1:0]	
External interrupt ch. 6		ГГГОН	FFF/H	LUZ [1.0]	
External interrupt ch. 3	IRQ03	FFF4 _H	FFF5H	L03 [1:0]	
External interrupt ch. 7		ГГГ4 Н	ГГГЭН	LU3 [1.0]	
—	IRQ04	FFF2H	FFF3⊦	L04 [1:0]	
8/16-bit composite timer ch. 0 (lower)	IRQ05	FFF0H	FFF1⊦	L05 [1:0]	
8/16-bit composite timer ch. 0 (upper)	IRQ06	FFEEH	FFEF⊦	L06 [1:0]	
LIN-UART (reception)	IRQ07	FFECH	FFEDH	L07 [1:0]	
LIN-UART (transmission)	IRQ08	FFEA H	FFEB H	L08 [1:0]	
—	IRQ09	FFE8H	FFE9⊦	L09 [1:0]	
—	IRQ10	FFE6H	FFE7н	L10 [1:0]	
—	IRQ11	FFE4H	FFE5H	L11 [1:0]	
—	IRQ12	FFE2H	FFE3H	L12 [1:0]	
—	IRQ13	FFE0H	FFE1н	L13 [1:0]	
8/16-bit composite timer ch. 1 (upper)	IRQ14	FFDEH	FFDFH	L14 [1:0]	
—	IRQ15	FFDC H	FFDDH	L15 [1:0]	
_	IRQ16	FFDA H	FFDB H	L16 [1:0]	
—	IRQ17	FFD8H	FFD9н	L17 [1:0]	
8/10-bit A/D converter	IRQ18	FFD6н	FFD7н	L18 [1:0]	
Time-base timer	IRQ19	FFD4 _H	FFD5H	L19 [1:0]	
Watch prescaler	IRQ20	FFD2H	FFD3H	L20 [1:0]	
_	IRQ21	FFD0н	FFD1н	L21 [1:0]	
8/16-bit composite timer ch. 1 (lower)	IRQ22	FFCEH	FFCFH	L22 [1:0]	↓
Flash memory	IRQ23	FFCC _H	FFCD H	L23 [1:0]	Low

■ INTERRUPT SOURCE TABLE (MB95570H Series)

		Vector tab	le address		Priority order of
Interrupt source	Interrupt request number	Upper	Lower	Bit name of interrupt level setting register	interrupt sources of the same level (occurring simultaneously)
External interrupt ch. 4	IRQ00	FFFA H	FFFB H	L00 [1:0]	High
_	IRQ01	FFF8⊦	FFF9н	L01 [1:0]	▲
—	IRQ02	FFF6 _H	FFF7н	L02 [1:0]	
External interrupt ch. 6	110202	TTTOH	11178	L02 [1.0]	
	IRQ03	FFF4 _H	FFF5⊦	L03 [1:0]	
_	IRQ04	FFF2H	FFF3H	L04 [1:0]	
8/16-bit composite timer ch. 0 (lower)	IRQ05	FFF0H	FFF1⊦	L05 [1:0]	
8/16-bit composite timer ch. 0 (upper)	IRQ06	FFEEH	FFEFH	L06 [1:0]	
—	IRQ07	FFECH	FFEDH	L07 [1:0]	
—	IRQ08	FFEAH	FFEBH	L08 [1:0]	
—	IRQ09	FFE8⊦	FFE9н	L09 [1:0]	
—	IRQ10	FFE6⊦	FFE7н	L10 [1:0]	
—	IRQ11	FFE4н	FFE5H	L11 [1:0]	
_	IRQ12	FFE2H	FFE3⊦	L12 [1:0]	
	IRQ13	FFE0H	FFE1⊦	L13 [1:0]	
_	IRQ14	FFDE H	FFDF H	L14 [1:0]	
	IRQ15	FFDC H	FFDDH	L15 [1:0]	
	IRQ16	FFDA H	FFDB H	L16 [1:0]	
—	IRQ17	FFD8⊦	FFD9⊦	L17 [1:0]	
8/10-bit A/D converter	IRQ18	FFD6н	FFD7н	L18 [1:0]	
Time-base timer	IRQ19	FFD4н	FFD5H	L19 [1:0]	
Watch prescaler	IRQ20	FFD2H	FFD3н	L20 [1:0]	
_	IRQ21	FFD0н	FFD1н	L21 [1:0]	
_	IRQ22	FFCEH	FFCF H	L22 [1:0]	♥
Flash memory	IRQ23	FFCC H	FFCD H	L23 [1:0]	Low

■ INTERRUPT SOURCE TABLE (MB95580H Series)

	1	Vector tab	le address		Priority order of	
Interrupt source	Interrupt request number	Upper	Lower	Bit name of interrupt level setting register	interrupt sources of the same level (occurring simultaneously)	
External interrupt ch. 4	IRQ00	FFFA H	FFFB⊦	L00 [1:0]	High	
External interrupt ch. 5	IRQ01	FFF8⊦	FFF9⊦	L01 [1:0]	▲	
External interrupt ch. 2	IRQ02	FFF6⊦	FFF7⊦	L02 [1:0]		
External interrupt ch. 6	110,02	TTTOH	11178	L02 [1.0]		
External interrupt ch. 3	IRQ03	FFF4 _H	FFF5H	L03 [1:0]		
External interrupt ch. 7		FFF4H	ГГГЭН	LU3 [1.0]		
	IRQ04	FFF2H	FFF3⊦	L04 [1:0]		
8/16-bit composite timer ch. 0 (lower)	IRQ05	FFF0H	FFF1⊦	L05 [1:0]		
8/16-bit composite timer ch. 0 (upper)	IRQ06	FFEEH	FFEFH	L06 [1:0]		
LIN-UART (reception)	IRQ07	FFECH	FFEDH	L07 [1:0]		
LIN-UART (transmission)	IRQ08	FFEAн	FFEBH	L08 [1:0]		
	IRQ09	FFE8⊦	FFE9⊦	L09 [1:0]		
	IRQ10	FFE6H	FFE7н	L10 [1:0]		
—	IRQ11	FFE4H	FFE5H	L11 [1:0]		
	IRQ12	FFE2H	FFE3H	L12 [1:0]		
	IRQ13	FFE0H	FFE1H	L13 [1:0]		
	IRQ14	FFDEH	FFDFH	L14 [1:0]		
	IRQ15	FFDC H	FFDDH	L15 [1:0]		
	IRQ16	FFDA H	FFDB H	L16 [1:0]		
	IRQ17	FFD8⊦	FFD9⊦	L17 [1:0]		
8/10-bit A/D converter	IRQ18	FFD6H	FFD7н	L18 [1:0]		
Time-base timer	IRQ19	FFD4H	FFD5H	L19 [1:0]		
Watch prescaler	IRQ20	FFD2H	FFD3H	L20 [1:0]		
—	IRQ21	FFD0н	FFD1н	L21 [1:0]		
_	IRQ22	FFCEH	FFCFH	L22 [1:0]] ♥	
Flash memory	IRQ23	FFCC _H	FFCDH	L23 [1:0]	Low	

■ ELECTRICAL CHARACTERISTICS

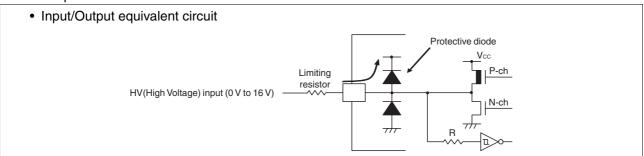
1. Absolute Maximum Ratings

Deremeter	Symbol	Rat	ing	فأحرارا	Bomoriko
Parameter	Symbol	Min	Max	Unit	Remarks
Power supply voltage*1	Vcc	$V_{\text{SS}}-0.3$	Vss+6	V	
Input voltage*1	V	$V_{\text{SS}} - 0.3$	Vss+6	V	*2
Output voltage*1	Vo	$V_{\text{SS}}-0.3$	Vss + 6	V	*2
Maximum clamp current		-2	+2	mA	Applicable to specific pins*3
Total maximum clamp current	Σ clamp	_	20	mA	Applicable to specific pins ^{*3}
"L" level maximum output current	lol	_	15	mA	
"L" level average current	IOLAV1	_	4	mA	Other than P00 to P03, P05 to P07, P62 to P64 ^{*4} Average output current= operating current \times operating ratio (1 pin)
	Iolav2		12		P00 to P03, P05 to P07, P62 to P64 ⁺⁴ Average output current= operating current × operating ratio (1 pin)
"L" level total maximum output current	ΣΙοι	_	48	mA	
"L" level total average output current	Σ Iolav	_	50	mA	Total average output current= operating current × operating ratio (Total number of pins)
"H" level maximum output current	Іон	_	-15	mA	
"H" level average current	Іонаν1		-4	mA	Other than P00 to P03, P05 to P07, P62 to P64 ^{*4} Average output current= operating current \times operating ratio (1 pin)
current	Іонау2		-8		P00 to P03, P05 to P07, P62 to P64 ^{*4} Average output current= operating current × operating ratio (1 pin)
"H" level total maximum output current	ΣІон	_	48	mA	
"H" level total average output current	ΣΙοήαν	_	-50	mA	Total average output current= operating current × operating ratio (Total number of pins)
Power consumption	P₫	—	320	mW	
Operating temperature	TA	-40	+85	°C	
Storage temperature	Tstg	-55	+150	°C	



(Continued)

- *1: These parameters are based on the condition that V_{SS} is 0.0 V.
- *2: VI and Vo must not exceed Vcc + 0.3 V. VI must not exceed the rated voltage. However, if the maximum current to/from an input is limited by means of an external component, the IcLAMP rating is used instead of the VI rating.
- *3: Applicable to the following pins: P00 to P07, P62 to P64, PF0, PF1, PG1, PG2 (P00, and P62 to P64 are only available on MB95F562H/F562K/F563H/F563K/F564H/F564K. P01, P02, P03, P07, PF0. PF1, PG1, and PG2 are only available on MB95F562H/F562K/F563H/F563K/F564H/F564K/F582H/F582K/F583H/F583K/F584H/F584K.)
 - Use under recommended operating conditions.
 - Use with DC voltage (current).
 - The HV (High Voltage) signal is an input signal exceeding the Vcc voltage. Always connect a limiting resistor between the HV (High Voltage) signal and the microcontroller before applying the HV (High Voltage) signal.
 - The value of the limiting resistor should be set to a value at which the current to be input to the microcontroller pin when the HV (High Voltage) signal is input is below the standard value, irrespective of whether the current is transient current or stationary current.
 - When the microcontroller drive current is low, such as in low power consumption modes, the HV (High Voltage) input potential may pass through the protective diode to increase the potential of the Vcc pin, affecting other devices.
 - If the HV (High Voltage) signal is input when the microcontroller power supply is off (not fixed at 0 V), since power is supplied from the pins, incomplete operations may be executed.
 - If the HV (High Voltage) input is input after power-on, since power is supplied from the pins, the voltage of power supply may not be sufficient to enable a power-on reset.
 - Do not leave the HV (High Voltage) input pin unconnected.
 - Example of a recommended circuit:



*4: P62 and P63 are only available on MB95F562H/F562K/F563H/F563K/F564H/F564K.

WARNING: Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

2. Recommended Operating Conditions

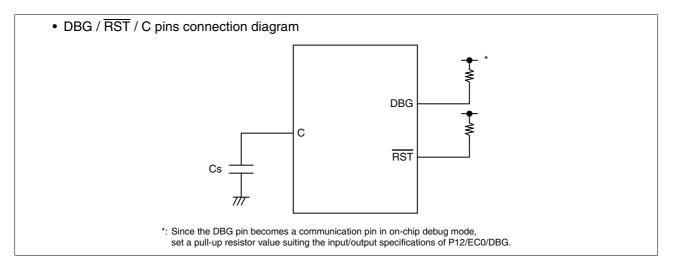
(Vss = 0.0 V)

Devementer	Cumbal	Va	lue	11	Remarks				
Parameter	Symbol	Min	Max	Unit	Rem	larks			
		2.4*1*2	5.5* ¹		In normal operation	Other than on-chip debug			
Power supply	Vcc	2.3	5.5	v	Hold condition in stop mode	mode			
voltage	VCC	2.9	5.5	v	In normal operation	On ahin dahug mada			
		2.3	5.5		Hold condition in stop mode	On-chip debug mode			
Decoupling capacitor	Cs	0.022	1	μF	*3				
Operating	TA	-40	+85	°C	Other than on-chip debug me	ode			
temperature	IA	+5	+35		On-chip debug mode				

*1: The value varies depending on the operating frequency, the machine clock and the analog guaranteed range.

*2: The value is 2.88 V when the low-voltage detection reset is used.

*3: Use a ceramic capacitor or a capacitor with equivalent frequency characteristics. The bypass capacitor for the V_{CC} pin must have a capacitance larger than C_s. For the connection to a decoupling capacitor C_s, see the diagram below. To prevent the device from unintentionally entering an unknown mode due to noise, minimize the distance between the C pin and C_s and the distance between C_s and the V_{ss} pin when designing the layout of a printed circuit board.



WARNING: The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated within these ranges.

Always use semiconductor devices within their recommended operating condition ranges. Operation outside these ranges may adversely affect reliability and could result in device failure.

No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their representatives beforehand.

3. DC Characteristics

	r		(Vcc = 5.0	V ± 109	‰, Vss = 0.	0 V, I	$T_{A} = -40^{\circ}C \text{ to } +85^{\circ}C)$	
Parameter	Symbol	Pin name	Condition		Value		Unit	Remarks	
rarameter	Cymbol	i in name	Condition	Min	Тур	Мах	onic	Tientarks	
	VIH	P04	—	0.7 Vcc		Vcc + 0.3	V	Hysteresis input	
"H" level input voltage	Vins	P00 ^{*3} to P03 ^{*4} , P05 to P07 ^{*4} , P12, P62 to P64 ^{*3} , PF0 ^{*4} , PF1 ^{*4} , PG1 ^{*4} , PG2 ^{*4}	_	0.8 Vcc	_	Vcc + 0.3	V	Hysteresis input	
	Vінм	PF2	—	0.8 Vcc	—	Vcc + 0.3	V	Hysteresis input	
	Vı∟	P04	—	V ss - 0.3	_	0.3 Vcc	V	Hysteresis input	
"L" level input voltage	Vils	P00 ^{*3} to P03 ^{*4} , P05 to P07 ^{*4} , P12, P62 to P64 ^{*3} , PF0 ^{*4} , PF1 ^{*4} , PG1 ^{*4} , PG2 ^{*4}	_	Vss - 0.3	_	0.2 Vcc	v	Hysteresis input	
	VILM	PF2	—	V ss - 0.3	_	0.2 Vcc	V	Hysteresis input	
Open-drain output application voltage	VD	P12, PF2	_	Vss – 0.3	_	Vss + 5.5	v		
"H" level	Vон1	P04, PF0*4, PF1*4, PG1*4, PG2*4	Iон = -4 mA	Vcc - 0.5		_	v		
output voltage	Vон2	P00 ^{*3} to P03 ^{*4} , P05 to P07 ^{*4} , P62 to P64 ^{*3}	Іон = -8 mA	Vcc - 0.5	_	_	v		
"L" level output	V _{OL1}	P04, P12, PF0 to PF2* ⁴ , PG1* ⁴ , PG2* ⁴	lo∟ = 4 mA	_	_	0.4	v		
voltage	V _{OL2}	P00* ³ to P03* ⁴ , P05 to P07* ⁴ , P62 to P64* ³	lo∟ = 12 mA	_	_	0.4	v		
Input leak current (Hi-Z output leak current)	lu	All input pins	0.0 V < Vı < Vcc	-5	_	+5	μA	When pull-up resistance is disabled	
Pull-up resistance	Rpull	P00* ³ to P07*4, P62 to P64* ³ , PG1*4, PG2*4	Vi = 0 V	25	50	100	kΩ	When pull-up resistance is enabled	
Input capacitance	Cin	Other than Vcc and Vss	f = 1 MHz		5	15	pF		

(Vcc = 5.0 V \pm 10%, Vss = 0.0 V, T_A = -40°C to +85°C)

	0	Dia			Value			Demoster
Parameter	Symbol	Pin name	Condition	Min	Typ*1	Max*2	Unit	Remarks
			Fсн = 32 MHz Fмp = 16 MHz	_	3.5	4.4	mA	Except during Flash memory programming and erasing
	Icc		Main clock mode (divided by 2)	_	7.4	9.8	mA	During Flash memory programming and erasing
				—	5.1	6.4	mA	At A/D conversion
	Iccs	Vcc (External clock	$F_{CH} = 32 \text{ MHz}$ $F_{MP} = 16 \text{ MHz}$ Main sleep mode (divided by 2)	_	1.2	1.5	mA	
	IccL	operation)	$F_{CL} = 32 \text{ kHz}$ $F_{MPL} = 16 \text{ kHz}$ Subclock mode (divided by 2) $T_A = +25^{\circ}C$	_	65	71	μA	
Power supply current*5	Iccls*6		$F_{CL} = 32 \text{ kHz}$ $F_{MPL} = 16 \text{ kHz}$ Subsleep mode (divided by 2) $T_A = +25^{\circ}C$		5.4	7	μΑ	In deep standby mode
	Iccт*6		F _{CL} = 32 kHz Watch mode T _A = +25°C	_	4.8	6.9	μA	In deep standby mode
	ICCMCR	Vcc	F _{CRH} = 4 MHz F _{MP} = 4 MHz Main CR clock mode	_	1.1	1.4	mA	
	ICCSCR	Vic	Sub-CR clock mode (divided by 2) T _A = +25°C	_	58	64	μA	
	Ісстѕ		Fcн = 32 MHz Time-base timer mode T _A = +25°C	_	290	340		In deep standby mode
	Іссн	Vcc (External clock operation)	Main stop mode (single external clock product)/ Substop mode (dual external clock product) T _A = +25°C		4.1	6.5	μΑ	In deep standby mode (Continued)

(Vcc = 5.0 V \pm 10%, Vss = 0.0 V, TA = -40°C to +85°C)

(Continued)

 $(V_{CC} = 5.0 \text{ V} \pm 10\%, \text{ Vss} = 0.0 \text{ V}, \text{ T}_{A} = -40^{\circ}\text{C} \text{ to } +85^{\circ}\text{C})$

Parameter	Symbol	Pin name	Condition		Value		Unit	Remarks
Falametei	Symbol	Finname	Condition	Min	Typ*1	Max*2	onit	nemarks
	Ilvd		Current consumption for the low-voltage detection circuit	_	3.6	6.6	μA	
	Іскн		Current consumption for the main CR oscillator	_	220	280	μA	
Power supply current*5	ICRL	Vcc	Current consumption for the sub-CR oscillator oscillating at 100 kHz	_	5.1	9.3	μA	
	Instby		Current consumption difference between normal standby mode and deep standby mode $T_A = +25^{\circ}C$		20	30	μΑ	

*1: $V_{CC} = 5.0 \text{ V}, \text{ T}_{A} = +25^{\circ}\text{C}$

*2: $V_{CC} = 5.5 \text{ V}$, $T_A = +85^{\circ}C$ (unless otherwise specified)

*3: P00, P62, P63 and P64 are only available on MB95F562H/F562K/F563H/F563K/F564H/F564K.

- *4: P01, P02, P03, P07, PF0, PF1, PG1 and PG2 are only available on MB95F562H/F562K/F563H/F563K/ F564H/F564K/F582H/F582K/F583H/F583K/F584H/F584K.
- *5: The power supply current is determined by the external clock. When the low-voltage detection option is selected, the power-supply current will be the sum of adding the current consumption of the low-voltage detection circuit (ILVD) to one of the value from Icc to IccH. In addition, when both the low-voltage detection option and the CR oscillator are selected, the power supply current will be the sum of adding up the current consumption of the low-voltage detection circuit, the current consumption of the CR oscillators (ICRH, ICRL) and a specified value. In on-chip debug mode, the CR oscillator (ICRH) and the low-voltage detection circuit are always enabled, and current consumption therefore increases accordingly.
 - See "4. AC Characteristics: (1) Clock Timing" for FCH and FCL.
 - See "4. AC Characteristics: (2) Source Clock / Machine Clock" for FMP and FMPL.

*6: In sub-CR clock mode, the power supply current value is the sum of adding ICRL to ICCLS or ICCT. In addition, when the sub-CR clock mode is selected with FMPL being 50 kHz, the current consumption increases accordingly.

4. AC Characteristics

(1) Clock Timing

(Vcc = 2.4 V to 5.5 V, Vss = 0.0 V, T_A = -40^{\circ}C to +85°C)

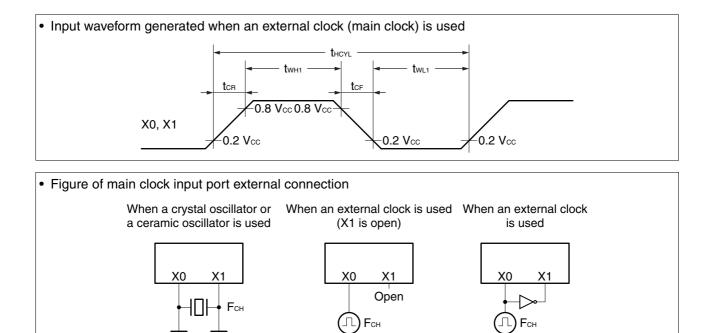
Frequency9.51010.5MHzPLL multiplier: 2.5 -40°C \leq TA < 0°C +70°C \leq TA < +85°C	Deremeter	Sumhal	Din nome	Condition		Value		ا ا	Domostko
$F_{CH} = \frac{F_{CH}}{F_{CH}} = \frac{F_{CH}}{F_{CH$	Parameter	Symbol	Pin name	Condition	Min	Тур	Max	Unit	
$F_{MCRPLL} $		FcH		—		_			circuit is used
Figure 3.92 4 4.08 MHz MHz - - Operating conditions + The main CR clock is used. · OPC ≤ TA < +70°C 3.8 4 4.2 MHz · - Operating conditions + The main CR clock is used. · -40°C ≤ TA < +70°C		I CH		-		—			
$ F_{\text{ICRPL}} = - + - + - + - + - + - + - + - + - + -$			X0, X1	*	1		32.5	MHz	
$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$					3.92	4	4.08		• The main CR clock is used.
$F_{MCRPLL} \left(\begin{array}{c} 7.84 \\ 8 \\ 7.84 \\ 8 \\ 8.16 \\ 10.2 \\ 8.10 \\ 9.8 \\ 10 \\ 10.2 \\ 10.2 \\ 8.10 \\ 10.2 \\ 8.10 \\ 10.2 \\ 8.10 \\ 10.2 \\ 8.10 \\ 10.2 \\ 8.10 \\ 10.2 \\ 8.10 \\ 10.2 \\ 8.10 \\ 10.2 \\ 8.10 \\ 10.2 \\ 8.10 \\ 10.2 \\ 8.10 \\ 10.2 \\ 8.10 \\ 10.2 \\ 8.10 \\ 10.2 $		Есвн			3.8	4	4.2		• The main CR clock is used. • $-40^{\circ}C \le T_A < 0^{\circ}C$
$ F_{MCRPLL} $					7.84	8	8.16		PLL multiplier: 2
$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$					7.6	8	8.4		 PLL multiplier: 2 -40°C ≤ T_A < 0°C
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $			_		9.8	10	10.2		PLL multiplier: 2.5
$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$	Clock frequency	-			9.5	10	10.5	MHZ	 PLL multiplier: 2.5 -40°C ≤ T_A < 0°C
$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$		FMCRPLL			11.76	12	12.24		PLL multiplier: 3
Image: FormationImage: XOA, X1AImage: Minimized matrixImage: Minimized matrix <td></td> <td></td> <td>11.4</td> <td>12</td> <td>12.6</td> <td></td> <td> PLL multiplier: 3 -40°C ≤ T_A < 0°C </td>					11.4	12	12.6		 PLL multiplier: 3 -40°C ≤ T_A < 0°C
FCLX0A, X1A $ 32.768$ $ kHz$ $^{\bullet}$ PLL multiplier: 4 $-40^{\circ}C \leq T_A < 0^{\circ}C$ $+70^{\circ}C \leq T_A < +85^{\circ}C$ FCLX0A, X1A $ 32.768$ $ kHz$ When the suboscillation circuit is usedFCR $ 32.768$ $ kHz$ When the suboscillation circuit is usedFCR $ 50$ 100 150 kHz When the sub-external clock is used					15.68	16	16.32	MHz	 PLL multiplier: 4 0°C ≤ T_A < +70°C
FCLX0A, X1A $ 32.768$ $ kHz$ is usedImage: FCLX0A, X1A $ 32.768$ $ kHz$ When the sub-external clock isImage: FCR $ 50$ 100 150 kHz When the sub-CR clock is					15.2	16	16.8		 PLL multiplier: 4 -40°C ≤ T_A < 0°C
- 32.768 - kHz When the sub-external clock is used ECRU - 50 100 150 kHz When the sub-CR clock is		Foi	X04 X14			32.768		kHz	When the suboscillation circuit is used
$ \mathbf{F}_{CB} - - 50 100 150 \mathbf{KH7} $		FCL	XUA, X1A	—	_	32.768	_	kHz	When the sub-external clock is used
		FCRL		_	50	100	150	kHz	

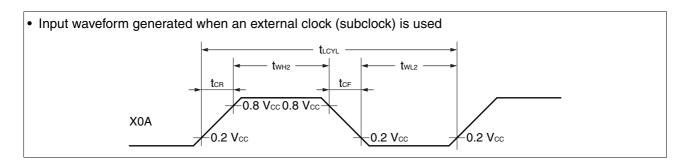
(Continued)				(V	′cc = 2.4	V to 5.	5 V , Vs	$s = 0.0 \text{ V}, \text{T}_{\text{A}} = -40^{\circ}\text{C} \text{ to } +85^{\circ}\text{C})$
Parameter	Symbol	Pin name	Condition		Value		Unit	Remarks
rarameter	Oymbol	i in name	Condition	Min	Тур	Max	Olin	nemarks
	.	X0, X1	_	61.5	_	1000	ns	When the main oscillation circuit is used
Clock cycle time	t HCYL	X0	X1 : open	83.4	—	1000	ns	When an external clock is
ume		X0, X1	*	30.8	—	1000	ns	used
	t LCYL	X0A, X1A	—		30.5		μs	When the subclock is used
	twH1	X0	X1 : open	33.4	—	—	ns	When an external clock is
Input clock	tw∟ı	X0, X1	*	12.4	—	—	ns	used, the duty ratio should
pulse width	twн₂ tw∟₂	X0A	_		15.2	_	μs	range between 40% and 60%.
Input clock rise	tся	X0	X1 : open		—	5	ns	When an external clock is
time and fall time	tcF	X0, X1	*		_	5		used
CR oscillation	t CRHWK	—	_	_	_	50	μs	When the main CR clock is used
start time	t crlwk		—	_	—	30	μs	When the sub-CR clock is used

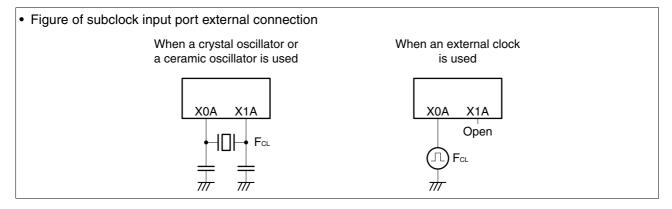
(Continued)

*: The external clock signal is input to X0 and the inverted external clock signal to X1.









(2) Source Clock / Machine Clock

 $(V_{CC} = 5.0 \text{ V} \pm 10\%, \text{ Vss} = 0.0 \text{ V}, \text{ T}_{A} = -40^{\circ}\text{C to } +85^{\circ}\text{C})$

Demonstern	Querra la cal	Pin		Value	,	11	$\pm 10\%, VSS = 0.0 V, TA = -40 C (0+03 C)$
Parameter	Symbol	name	Min	Тур	Max	Unit	Remarks
			61.5	_	2000	ns	When the main external clock is used Min: $F_{CH} = 32.5$ MHz, divided by 2 Max: $F_{CH} = 1$ MHz, divided by 2
Source clock cycle time*1	t sclk	_	62.5	_	1000	ns	When the main CR clock is used Min: $F_{CRH} = 4$ MHz, multiplied by 4 Max: $F_{CRH} = 4$ MHz, divided by 4
				61	_	μs	When the suboscillation clock is used $F_{CL} = 32.768 \text{ kHz}$, divided by 2
				20	_	μs	When the sub-CR clock is used $F_{CRL} = 100 \text{ kHz}$, divided by 2
	Fsp		0.5		16.25	MHz	When the main oscillation clock is used
Source clock	1 5P		_	4		MHz	When the main CR clock is used
frequency		—	—	16.384	—	kHz	When the suboscillation clock is used
	Fspl		_	50	_	kHz	When the sub-CR clock is used $F_{CRL} = 100 \text{ kHz}$, divided by 2
			61.5	_	32000	ns	When the main oscillation clock is used Min: $F_{SP} = 16.25$ MHz, no division Max: $F_{SP} = 0.5$ MHz, divided by 16
Machine clock cycle time* ² (minimum	tмс⊧к		250	_	1000	ns	When the main CR clock is used Min: $F_{SP} = 4$ MHz, no division Max: $F_{SP} = 4$ MHz, divided by 4
instruction execution time)	UMOLK		61		976.5	μs	When the suboscillation clock is used Min: $F_{SPL} = 16.384$ kHz, no division Max: $F_{SPL} = 16.384$ kHz, divided by 16
			20		320	μs	When the sub-CR clock is used Min: $F_{SPL} = 50$ kHz, no division Max: $F_{SPL} = 50$ kHz, divided by 16
	Fмр		0.031	—	16.25	MHz	When the main oscillation clock is used
Machine clock			0.25	_	16	MHz	When the main CR clock is used
frequency		—	1.024	_	16.384	kHz	When the suboscillation clock is used
	Fmpl		3.125		50	kHz	When the sub-CR clock is used $F_{CRL} = 100 \text{ kHz}$

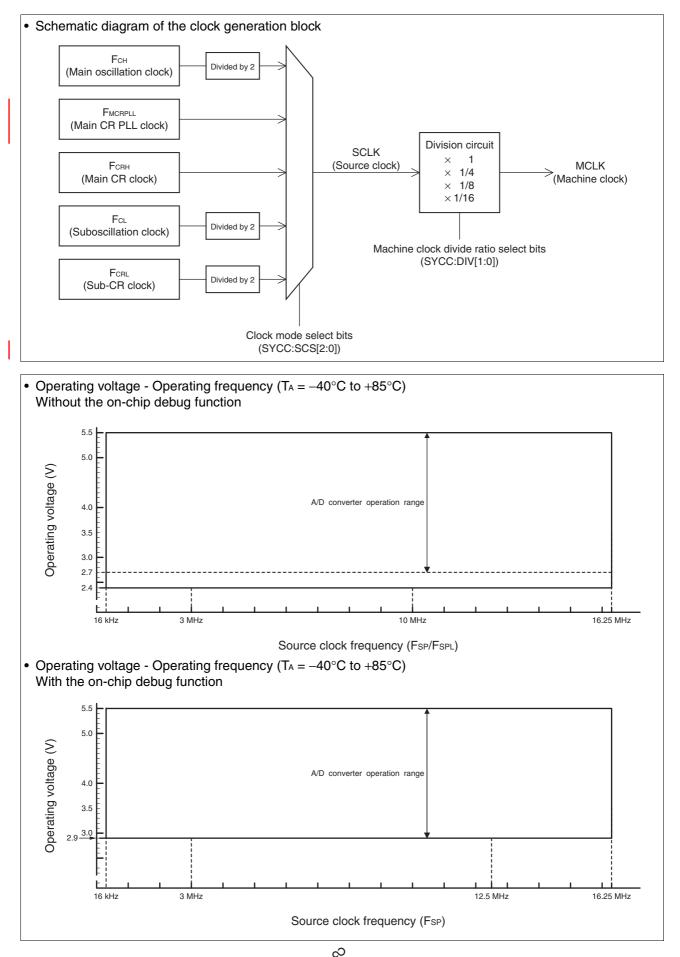
*1: This is the clock before it is divided according to the division ratio set by the machine clock division ratio select bits (SYCC:DIV[1:0]). This source clock is divided to become a machine clock according to the division ratio set by the machine clock division ratio select bits (SYCC:DIV[1:0]). In addition, a source clock can be selected from the following.

- Main clock divided by 2
- PLL multiplication of main CR clock (Select a multiplier from 2, 2.5, 3 and 4.)
- Main CR clock
- Subclock divided by 2
- Sub-CR clock divided by 2

*2: This is the operating clock of the microcontroller. A machine clock can be selected from the following.

- Source clock (no division)
- Source clock divided by 4
- Source clock divided by 8
- Source clock divided by 16





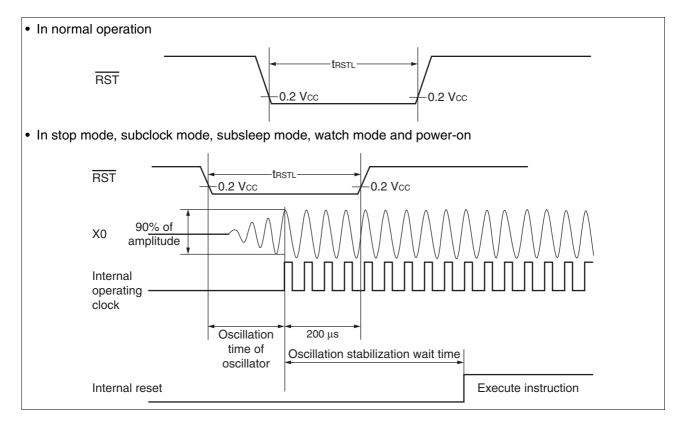
(3) External Reset

 $(V_{CC} = 5.0 \text{ V} \pm 10\%, \text{ V}_{SS} = 0.0 \text{ V}, \text{ T}_{A} = -40^{\circ}\text{C to } +85^{\circ}\text{C})$

Parameter	Symbol	Value			Remarks	
Farameter	eter Symbol Min Max U		Unit	nemarks		
		2 tмськ*1	—	ns	In normal operation	
RST "L" level pulse width	t rstl	Oscillation time of the oscillator*2 + 200	_	μs	In stop mode, subclock mode, subsleep mode, watch mode, and power-on	
		200		μs	In time-base timer mode	

*1: See "(2) Source Clock / Machine Clock" for tmclk.

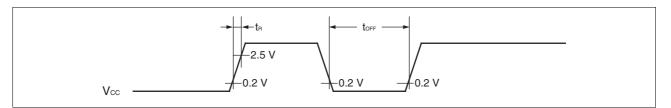
*2: The oscillation time of an oscillator is the time for it to reach 90% of its amplitude. The crystal oscillator has an oscillation time of between several ms and tens of ms. The ceramic oscillator has an oscillation time of between hundreds of µs and several ms. The external clock has an oscillation time of 0 ms. The CR oscillator has an oscillation time of between several µs and several ms.



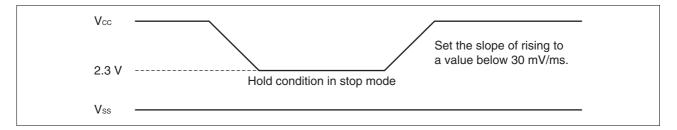
(4) Power-on Reset

 $(V_{SS} = 0.0 \text{ V}, \text{ T}_{A} = -40^{\circ}\text{C to } +85^{\circ}\text{C})$

Parameter	Symbol	Condition	Va	lue	Unit	Remarks
Falameter	Symbol	Condition	Min	Max	Onit	nemarks
Power supply rising time	tR	—	_	50	ms	
Power supply cutoff time	toff		1		ms	Wait time until power-on



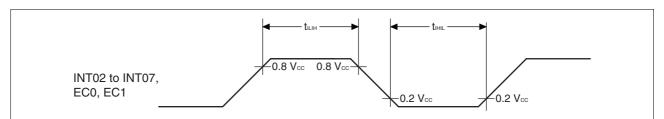
Note: A sudden change of power supply voltage may activate the power-on reset function. When changing the power supply voltage during the operation, set the slope of rising to a value below within 30 mV/ms as shown below.



(5) Peripheral Input Timing

 $(V_{CC} = 5.0 \text{ V} \pm 10\%, \text{ Vss} = 0.0 \text{ V}, \text{ T}_{A} = -40^{\circ}\text{C} \text{ to } +85^{\circ}\text{C})$

Parameter	Symbol	Pin name	Va	Value	
Falameter	Symbol	Fininanie	Min	Max	Unit
Peripheral input "H" pulse width	se width tune INT02 to INT07*1,*2, EC0*1,		2 t MCLK*4	—	ns
Peripheral input "L" pulse width	tını∟		2 t MCLK*4	_	ns



*1: INT04, INT06 and EC0 are available on all products.

*2: INT02, INT03, INT05 and INT07 are only available on MB95F562H/F562K/F563H/F563K/F564H/F564K/ F582H/F582K/F583H/F583K/F584H/F584K.

*3: EC1 is only available on MB95F562H/F562K/F563H/F563K/F564H/F564K.

*4: See "(2) Source Clock / Machine Clock" for tmclk.

(6) LIN-UART Timing (only available on MB95F562H/F562K/F563H/F563K/F564H/F564K/F582H/F582K/ F583H/F583K/F584H/F584K)

Sampling is executed at the rising edge of the sampling clock^{*1}, and serial clock delay is disabled^{*2}. (ESCR register: SCES bit = 0, ECCR register: SCDE bit = 0) $(V_{CC} = 5.0 \text{ V} \pm 10\%, \text{ AV}_{SS} = \text{V}_{SS} = 0.0 \text{ V}, \text{ T}_{A} = -40^{\circ}\text{C} \text{ to } +85^{\circ}\text{C})$

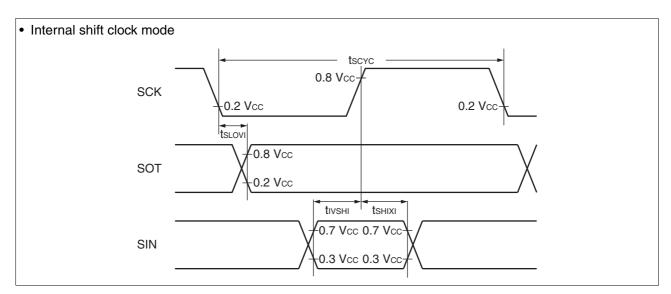
Parameter	Symbol	Pin name	Condition	Va	lue	Unit
Parameter	Symbol	Fin hame	Condition	Min	Max	Unit
Serial clock cycle time	tscyc	SCK		5 t мськ* ³	—	ns
SCK $\downarrow \rightarrow$ SOT delay time	tslovi	SCK, SOT	Internal clock	-50	+50	ns
Valid SIN \rightarrow SCK \uparrow	tıvsнı	SCK, SIN	operation output pin: C∟ = 80 pF + 1 TTL	tмськ*3 + 80	—	ns
SCK $\uparrow \rightarrow$ valid SIN hold time	tshixi	SCK, SIN		0	—	ns
Serial clock ?L? pulse width	tslsh	SCK		$3 t_{\text{MCLK}^{\star 3}} - t_{\text{R}}$	—	ns
Serial clock ?H? pulse width	tshsl	SCK		tмськ*3 + 10	—	ns
SCK $\downarrow \rightarrow$ SOT delay time	tslove	SCK, SOT	External clock	_	2 tмськ*3 + 60	ns
Valid SIN \rightarrow SCK \uparrow	tivshe	SCK, SIN	operation output pin:	30	—	ns
SCK $\uparrow \rightarrow$ valid SIN hold time	tshixe	SCK, SIN	C∟ = 80 pF + 1 TTL	tмськ*3 + 30	—	ns
SCK fall time	t⊧	SCK		—	10	ns
SCK rise time	tR	SCK		_	10	ns

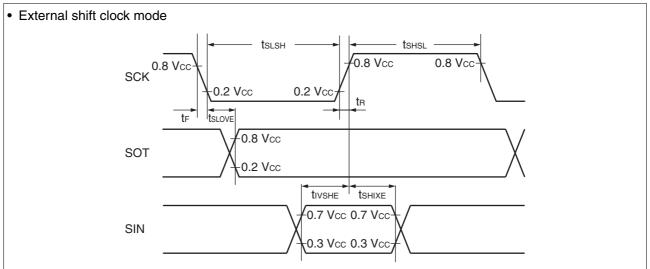
*1: There is a function used to choose whether the sampling of reception data is performed at a rising edge or a falling edge of the serial clock.

*2: The serial clock delay function is a function used to delay the output signal of the serial clock for half the clock.

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*3: See "(2) Source Clock / Machine Clock" for tmclk.





Sampling is executed at the falling edge of the sampling $clock^{*1}$, and serial clock delay is disabled^{*2}. (ESCR register: SCES bit = 1, ECCR register: SCDE bit = 0)

(Vcc = 5.0 V \pm 10%, Vss = 0.0 V, T_A = -40°C to +85°C)

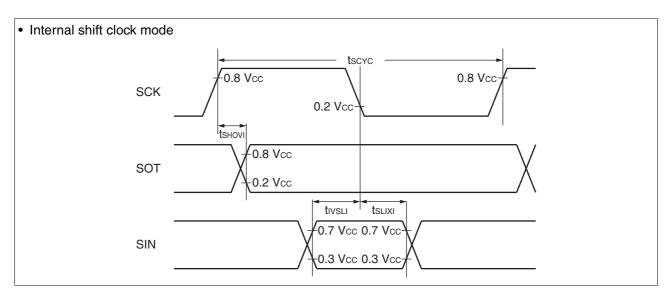
Parameter	Symbol	Pin name	Condition	Va	lue	Unit
Farameter	Symbol	Fin hame	Condition	Min	in Max	
Serial clock cycle time	tscyc	SCK		5 t мськ* ³	—	ns
SCK $\uparrow \rightarrow$ SOT delay time	tshovi	SCK, SOT	Internal clock operation output pin:	-50	+50	ns
Valid SIN $ ightarrow$ SCK \downarrow	tivsli	SCK, SIN	$C_{L} = 80 \text{ pF} + 1 \text{ TTL}$	tмськ*3 + 80	—	ns
SCK $\downarrow \rightarrow$ valid SIN hold time	tslixi	SCK, SIN	•	0	—	ns
Serial clock ?H? pulse width	tshsl	SCK		$3 t_{\text{MCLK}^{\star 3}} - t_{\text{R}}$	—	ns
Serial clock ?L? pulse width	tslsh	SCK		tмськ*3 + 10	—	ns
SCK $\uparrow \rightarrow$ SOT delay time	t shove	SCK, SOT	External clock		2 tмськ*3 + 60	ns
Valid SIN $ ightarrow$ SCK \downarrow	tivsle	SCK, SIN	operation output pin:	30	—	ns
SCK $\downarrow \rightarrow$ valid SIN hold time	tslixe	SCK, SIN	C∟ = 80 pF + 1 TTL	tмськ*3 + 30	—	ns
SCK fall time	t⊧	SCK		—	10	ns
SCK rise time	tR	SCK		_	10	ns

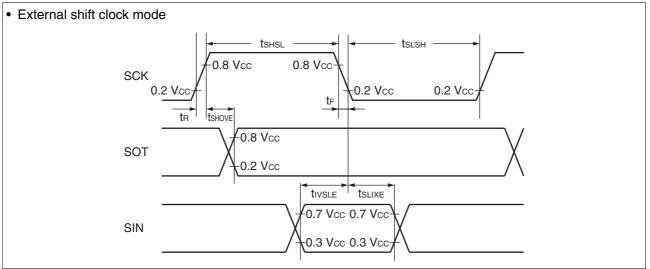
*1: There is a function used to choose whether the sampling of reception data is performed at a rising edge or a falling edge of the serial clock.

*2: The serial clock delay function is a function used to delay the output signal of the serial clock for half the clock.

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*3: See "(2) Source Clock / Machine Clock" for tmclk.





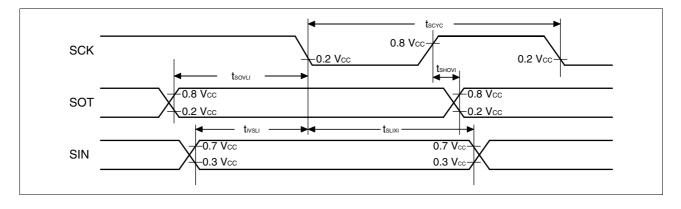
Sampling is executed at the rising edge of the sampling $clock^{*1}$, and serial clock delay is enabled^{*2}. (ESCR register: SCES bit = 0, ECCR register: SCDE bit = 1)

		-	$(Vcc = 5.0 V \pm 10\%)$	Vss = 0.0 V, T	$A = -40^{\circ}C$ to -	-85°C)
Parameter	Symbol	Pin name	Condition	Va	ue	Unit
Farameter	Symbol	Fin hame	Condition	Min	Max	Unit
Serial clock cycle time	tscyc	SCK		5 t мськ* ³	_	ns
SCK $\uparrow \rightarrow$ SOT delay time	t shovi	SCK, SOT	Internal clock	-50	+50	ns
$Valid\;SIN\toSCK\downarrow$	tivsli	SCK, SIN	operation output pin:	tмськ*3 + 80	_	ns
SCK $\downarrow \rightarrow$ valid SIN hold time	tslixi	SCK, SIN	C∟ = 80 pF + 1 TTL	0	_	ns
$SOT \to SCK \downarrow delay time$	tsovli	SCK, SOT		$3 t$ MCLK $^{*3} - 70$		ns

*1: There is a function used to choose whether the sampling of reception data is performed at a rising edge or a falling edge of the serial clock.

*2: The serial clock delay function is a function that delays the output signal of the serial clock for half clock.

*3: See "(2) Source Clock / Machine Clock" for tmclk.



Sampling is executed at the falling edge of the sampling $clock^{*1}$, and serial clock delay is enabled^{*2}. (ESCR register: SCES bit = 1, ECCR register: SCDE bit = 1)

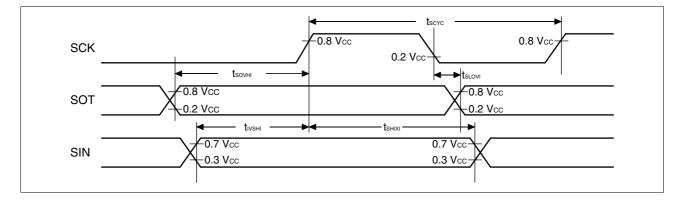
 $(V_{CC} = 5.0 \text{ V} \pm 10\%, \text{ Vss} = 0.0 \text{ V}, \text{ T}_{A} = -40^{\circ}\text{C} \text{ to } +85^{\circ}\text{C})$

Parameter	Symbol	Pin name	Condition	Va	Unit	
Farameter	Symbol	Fin name	Condition	Min	Max	Unit
Serial clock cycle time	tscyc	SCK		5 t мськ* ³	_	ns
SCK $\downarrow \rightarrow$ SOT delay time	tslovi	SCK, SOT	Internal clock	-50	+50	ns
Valid SIN \rightarrow SCK \uparrow	tivshi	SCK, SIN	operating output pin:	t мськ*3 + 80	_	ns
SCK $\uparrow \rightarrow$ valid SIN hold time	tshixi	SCK, SIN	C∟ = 80 pF + 1 TTL	0	_	ns
$SOT \to SCK \uparrow delay time$	tsovнı	SCK, SOT		3 tмськ*3 – 70	—	ns

*1: There is a function used to choose whether the sampling of reception data is performed at a rising edge or a falling edge of the serial clock.

*2: The serial clock delay function is a function that delays the output signal of the serial clock for half clock.

*3: See "(2) Source Clock / Machine Clock" for tmclk.



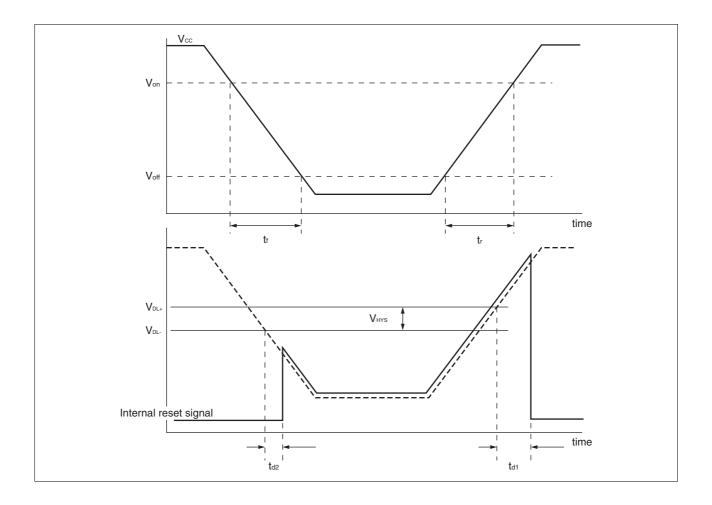
(7) Low-voltage Detection

(Vss = 0.0 V, $T_A = -40^{\circ}C$ to +85°C)

Parameter	Symbol		Value		Unit	Remarks
Falameter	Symbol	Min	Тур	Мах	Unit	nelliaiks
		2.52	2.7	2.88		
Release voltage*	V _{DL+}	2.61	2.8	2.99	v	At power supply rise
helease vollage	V DL+	2.89	3.1	3.31	v	At power supply lise
		3.08	3.3	3.52		
		2.43	2.6	2.77		
Detection voltage*	V _{DL} _	2.52	2.7	2.88	v	At power supply fall
Delection voltage	V DL-	2.80	3	3.20	v	At power suppry rain
		2.99	3.2	3.41		
Hysteresis width	VHYS	_	100		mV	
Power supply start voltage	Voff	_	_	2.3	V	
Power supply end voltage	Von	4.9	_		V	
Power supply voltage change time (at power supply rise)	tr	650	_	_	μs	Slope of power supply that the reset release signal generates within the rating (V_{DL+})
Power supply voltage change time (at power supply fall)	tr	650			μs	Slope of power supply that the reset detection signal generates within the rating (V_{DL} -)
Reset release delay time	t _{d1}			30	μs	
Reset detection delay time	t _{d2}			30	μs	
LVD threshold voltage transition stabilization time	tstb	10			μs	

*: The release voltage and the detection voltage can be selected by using the LVD reset voltage selection ID register (LVDR) in the low-voltage detection reset circuit. For details of the LVDR register, refer to "CHAPTER 18 LOW-VOLTAGE DETECTION RESET CIRCUIT" in the hardware manual of the MB95560H/ 570H/580H Series.





5. A/D Converter

(1) A/D Converter Electrical Characteristics

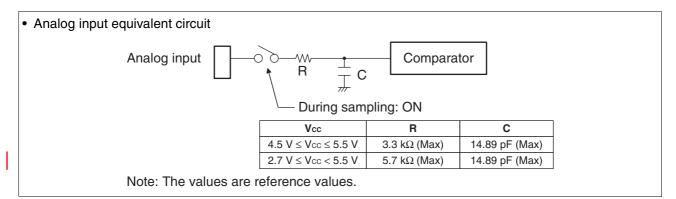
(Vcc = 2.7 V to 5.5 V, Vss = 0.0 V, $T_A = -40^{\circ}C$ to +85°C)

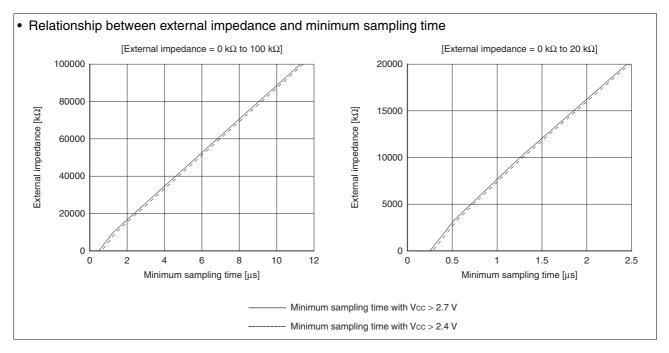
Parameter	Symbol		Value		Unit	Remarks
Farameter	Symbol	Min Typ		Max	Unit	neillaiks
Resolution		—	—	10	bit	
Total error		-3	—	+3	LSB	
Linearity error	—	-2.5	—	+2.5	LSB	
Differential linearity error		-1.9	_	+1.9	LSB	
Zero transition voltage	Vот	Vss – 1.5 LSB	Vss + 0.5 LSB	Vss + 2.5 LSB	V	
Full-scale transition voltage	VFST	Vcc – 4.5 LSB	Vcc – 2 LSB	Vcc + 0.5 LSB	V	
Compare time		1		10	μs	$4.5 \text{ V} \leq V_{CC} \leq 5.5 \text{ V}$
Compare time	_	3	—	10	μs	$2.7 \text{ V} \leq \text{Vcc} < 4.5 \text{ V}$
Sampling time		0.6	_	×	μs	$\begin{array}{l} \text{2.7 V} \leq V_{CC} \leq 5.5 \text{ V},\\ \text{with external}\\ \text{impedance} < 3.3 \text{ k}\Omega \end{array}$
Analog input current	Iain	-0.3	—	+0.3	μA	
Analog input voltage	VAIN	Vss	—	Vcc	V	

(2) Notes on Using A/D Converter

• External impedance of analog input and its sampling time

The A/D converter has a sample and hold circuit. If the external impedance is too high to keep sufficient sampling time, the analog voltage charged to the capacitor of the internal sample and hold circuit is insufficient, adversely affecting A/D conversion precision. Therefore, to satisfy the A/D conversion precision standard, considering the relationship between the external impedance and minimum sampling time, either adjust the register value and operating frequency or decrease the external impedance so that the sampling time is longer than the minimum value. In addition, if sufficient sampling time cannot be secured, connect a capacitor of about 0.1 μ F to the analog input pin.





• A/D conversion error

As IVcc - VssI decreases, the A/D conversion error increases proportionately.

(3) Definitions of A/D Converter Terms

Resolution

It indicates the level of analog variation that can be distinguished by the A/D converter. When the number of bits is 10, analog voltage can be divided into $2^{10} = 1024$.

• Linearity error (unit: LSB)

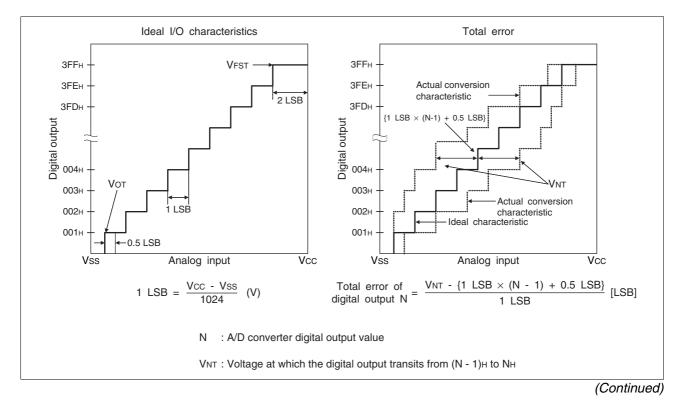
It indicates how much an actual conversion value deviates from the straight line connecting the zero transition point ("0000000000" $\leftarrow \rightarrow$ "0000000001") of a device to the full-scale transition point ("1111111111" $\leftarrow \rightarrow$ "1111111110") of the same device.

• Differential linear error (unit: LSB)

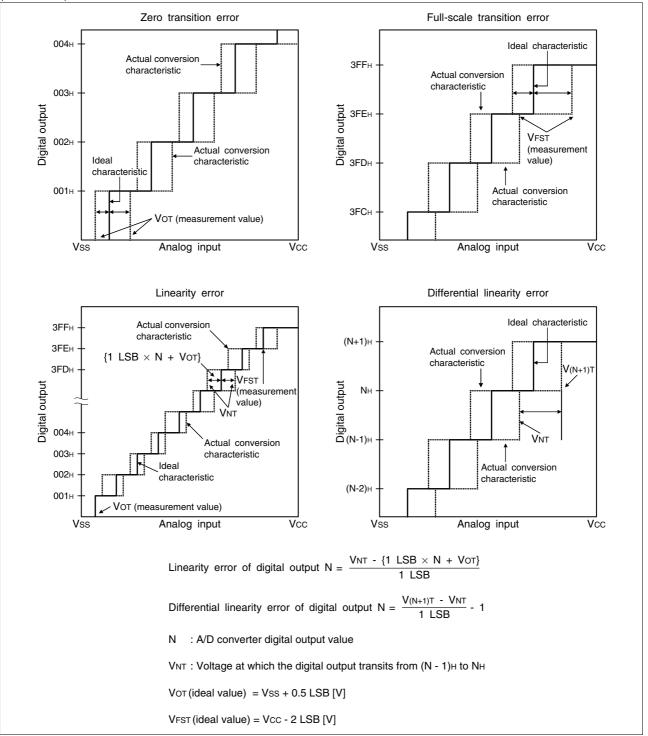
It indicates how much the input voltage required to change the output code by 1 LSB deviates from an ideal value.

• Total error (unit: LSB)

It indicates the difference between an actual value and a theoretical value. The error can be caused by a zero transition error, a full-scale transition errors, a linearity error, a quantum error, or noise.







6. Flash Memory Program/Erase Characteristics

Parameter		Value		Unit	Remarks
Falailletei	Min Typ Max		Unit	nelliaiks	
Sector erase time (2 Kbyte sector)	—	0.3* ¹	1.6* ²	s	The time of writing 00⊦ prior to erasure is excluded.
Sector erase time (16 Kbyte sector)	_	0.6*1	3.1* ²	s	The time of writing 00⊦ prior to erasure is excluded.
Byte writing time	_	17	272	μs	System-level overhead is excluded.
Program/erase cycle	100000	_		cycle	
Power supply voltage at program/erase	2.4	_	5.5	V	
Flash memory data retention time	5* ³	_	_	year	Average T _A = +85°C

*1: $V_{CC} = 5.5 \text{ V}, \text{ T}_{A} = +25^{\circ}\text{C}, \text{ 0 cycle}$

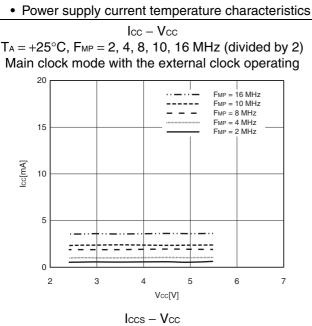
*2: $V_{CC} = 2.4 \text{ V}$, $T_A = +85^{\circ}C$, 100000 cycles

*3: This value was converted from the result of a technology reliability assessment. (The value was converted from the result of a high temperature accelerated test using the Arrhenius equation with an average temperature of +85°C).

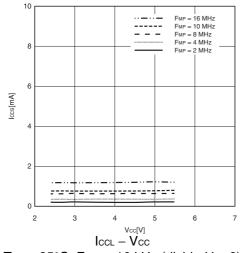
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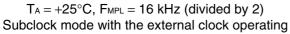
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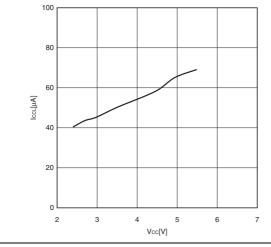
SAMPLE CHARACTERISTICS



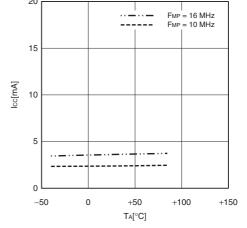
 $T_A = +25^{\circ}C$, $F_{MP} = 2, 4, 8, 10, 16 \text{ MHz}$ (divided by 2) Main sleep mode with the external clock operating





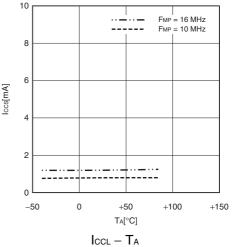


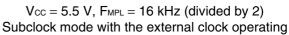
Icc – Ta Vcc = 5.5 V, F_{MP} = 10, 16 MHz (divided by 2) Main clock mode with the external clock operating 20

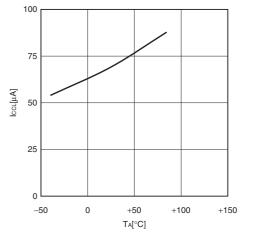


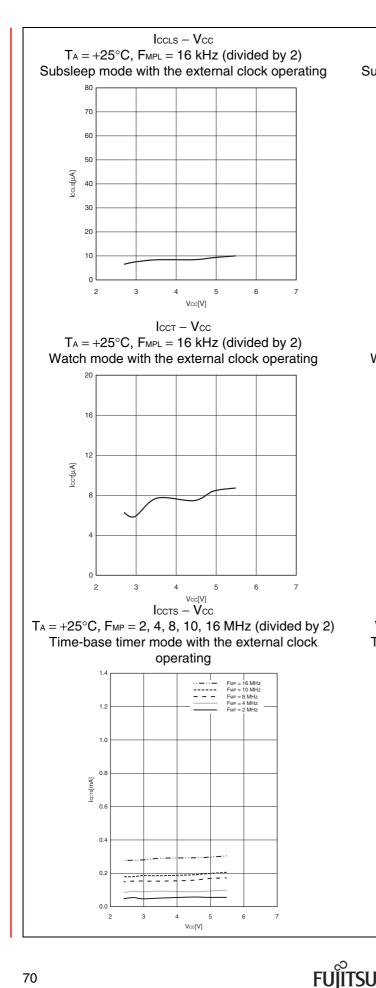


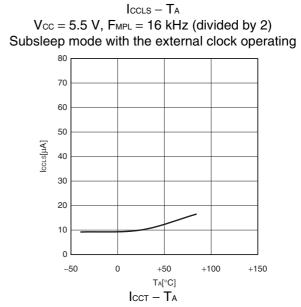
 $V_{CC} = 5.5 \text{ V}, \text{ F}_{MP} = 10, 16 \text{ MHz}$ (divided by 2) Main sleep mode with the external clock operating

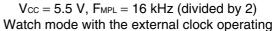


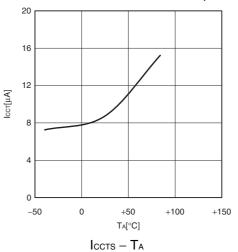


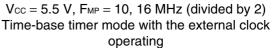


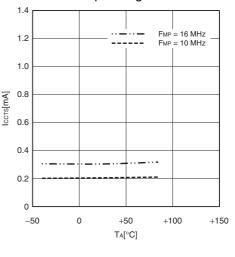


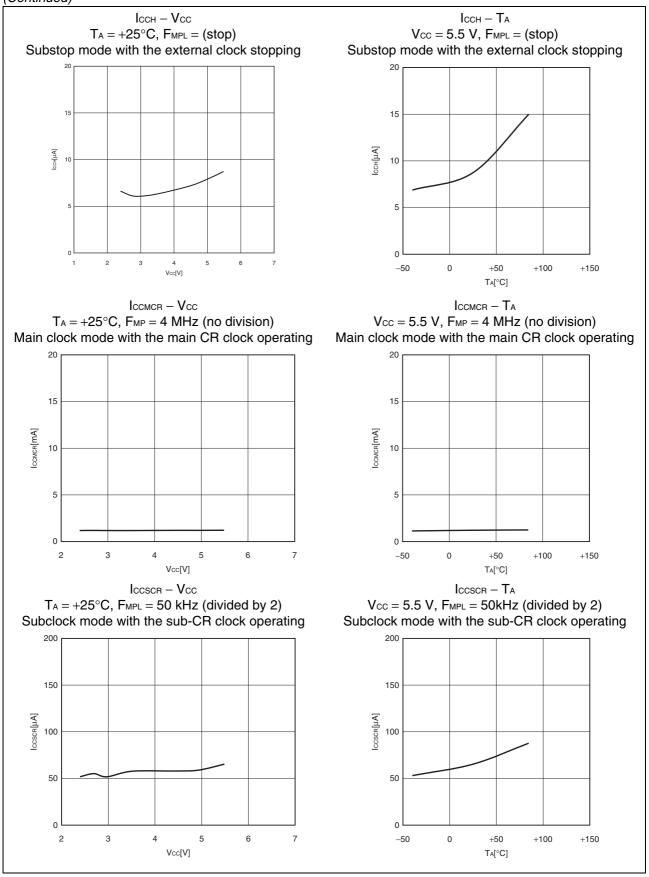


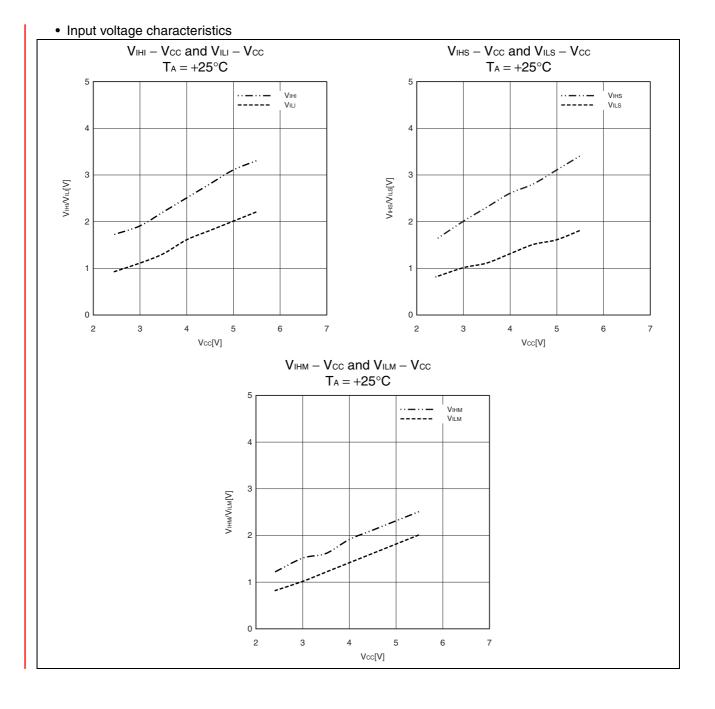


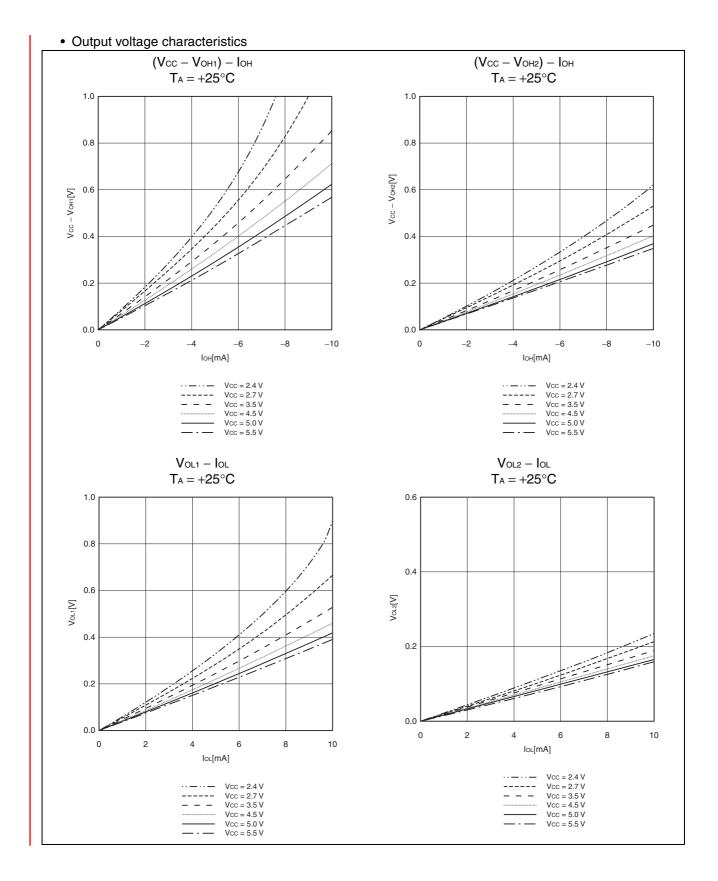




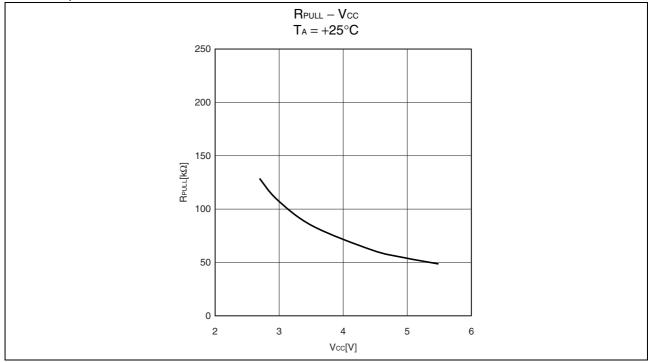








• Pull-up characteristics



■ MASK OPTIONS

		MDOFECOLL		
	Part Number	MB95F562H	MB95F562K	
		MB95F563H	MB95F563K	
		MB95F564H	MB95F564K	
		MB95F572H	MB95F572K	
		MB95F573H	MB95F573K	
No.		MB95F574H	MB95F574K	
		MB95F582H	MB95F582K	
		MB95F583H	MB95F583K	
		MB95F584H	MB95F584K	
	Selectable/Fixed	Fixed		
1	Low-voltage detection reset	Without low-voltage detection reset	With low-voltage detection reset	
2	Reset	With dedicated reset input	Without dedicated reset input	



■ ORDERING INFORMATION

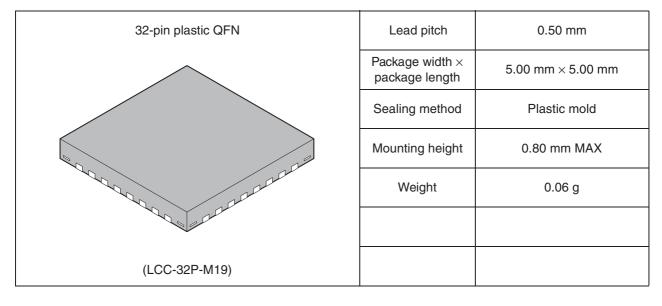
Part number	Package
MB95F562HWQN-G-SNE1	
MB95F562HWQN-G-SNERE1	
MB95F562KWQN-G-SNE1	
MB95F562KWQN-G-SNERE1	
MB95F563HWQN-G-SNE1	
MB95F563HWQN-G-SNERE1	32-pin plastic QFN
MB95F563KWQN-G-SNE1	(LCC-32P-M19)
MB95F563KWQN-G-SNERE1	
MB95F564HWQN-G-SNE1	
MB95F564HWQN-G-SNERE1	
MB95F564KWQN-G-SNE1	
MB95F564KWQN-G-SNERE1	
MB95F562HPF-G-SNE2	
MB95F562KPF-G-SNE2	
MB95F562KFF-G-SNE2 MB95F563HPF-G-SNE2	20-nin plactic SOP
	20-pin plastic SOP
MB95F563KPF-G-SNE2	(FPT-20P-M09)
MB95F564HPF-G-SNE2	
MB95F564KPF-G-SNE2	
MB95F562HPFT-G-SNE2	
MB95F562KPFT-G-SNE2	
MB95F563HPFT-G-SNE2	20-pin plastic TSSOP
MB95F563KPFT-G-SNE2	(FPT-20P-M10)
MB95F564HPFT-G-SNE2	
MB95F564KPFT-G-SNE2	
MB95F582HWQN-G-SNE1	
MB95F582HWQN-G-SNERE1	
MB95F582KWQN-G-SNE1	
MB95F582KWQN-G-SNERE1	
MB95F583HWQN-G-SNE1	
MB95F583HWQN-G-SNERE1	32-pin plastic QFN
MB95F583KWQN-G-SNE1	(LCC-32P-M19)
MB95F583KWQN-G-SNERE1	```''
MB95F584HWQN-G-SNE1	
MB95F584HWQN-G-SNERE1	
MB95F584KWQN-G-SNE1	
MB95F584KWQN-G-SNERE1	
MB95F582HPFT-G-SNE2	
MB95F582KPFT-G-SNE2	
MB95F583HPFT-G-SNE2	16-pin plastic TSSOP
MB95F583KPFT-G-SNE2	(FPT-16P-M08)
MB95F584HPFT-G-SNE2	
MB95F584KPFT-G-SNE2	
MB95F582HPF-G-SNE2	
MB95F582KPF-G-SNE2	
MB95F583HPF-G-SNE2	16-pin plastic SOP
MB95F583KPF-G-SNE2	(FPT-16P-M23)
MB95F584HPF-G-SNE2 MB95F584KPF-G-SNE2	

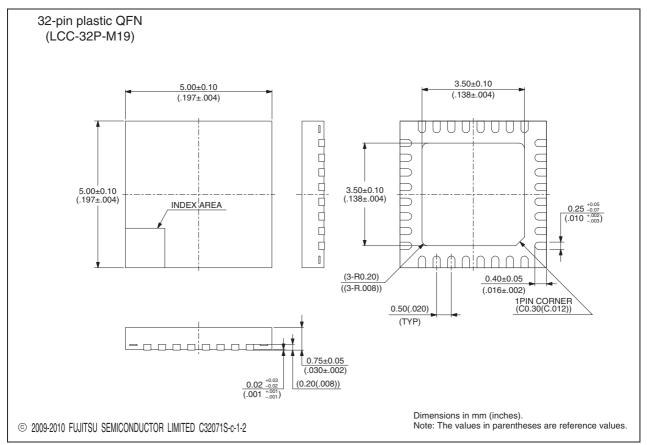
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Part number	Package	
MB95F572HPH-G-SNE2		
MB95F572KPH-G-SNE2		
MB95F573HPH-G-SNE2	8-pin plastic DIP	
MB95F573KPH-G-SNE2	(DIP-8P-M03)	
MB95F574HPH-G-SNE2		
MB95F574KPH-G-SNE2		
MB95F572HPF-G-SNE2		
MB95F572KPF-G-SNE2		
MB95F573HPF-G-SNE2	8-pin plastic SOP	
MB95F573KPF-G-SNE2	(FPT-8P-M08)	
MB95F574HPF-G-SNE2		
MB95F574KPF-G-SNE2		



■ PACKAGE DIMENSION

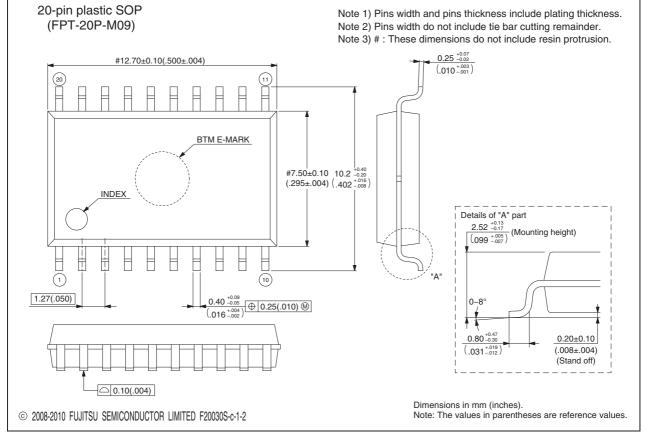




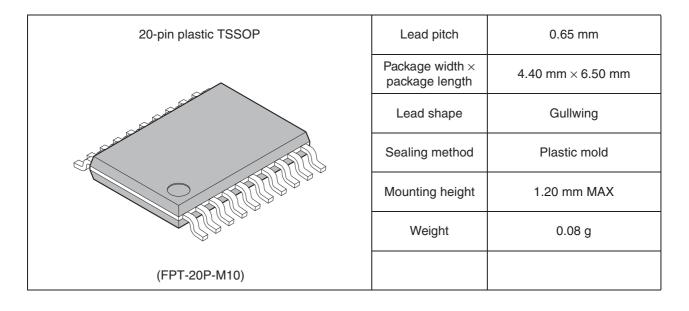
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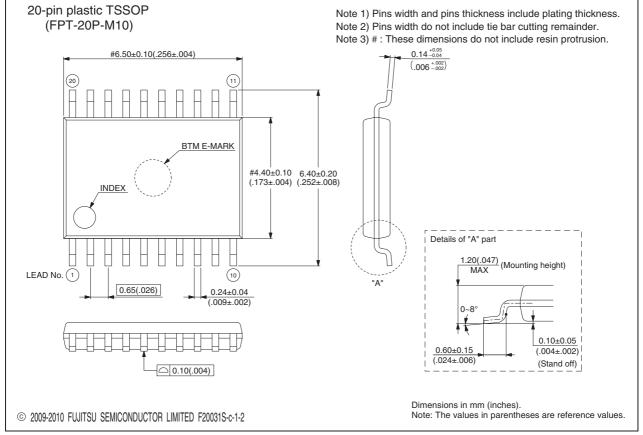
Please check the latest package dimension at the following URL. http://edevice.fujitsu.com/package/en-search/

20-pin plastic SOP	Lead pitch	1.27 mm
	Package width \times package length	7.50 mm × 12.70 mm
	Lead shape	Gullwing
A A A A A A A A A A A A A A A A A A A	Lead bend direction	Normal bend
ALT TILLE	Sealing method	Plastic mold
	Mounting height	2.65 mm Max
(FPT-20P-M09)		



Please check the latest package dimension at the following URL. http://edevice.fujitsu.com/package/en-search/

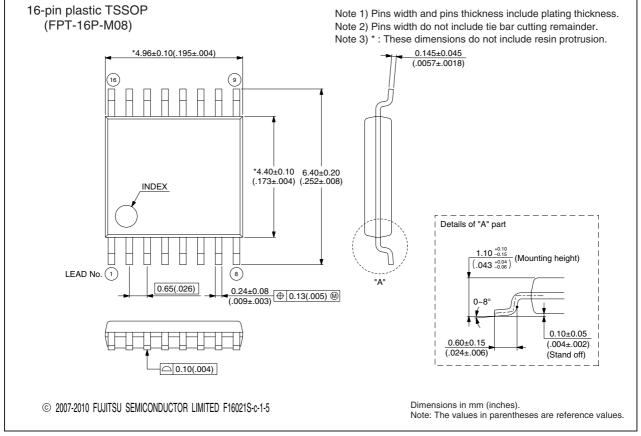




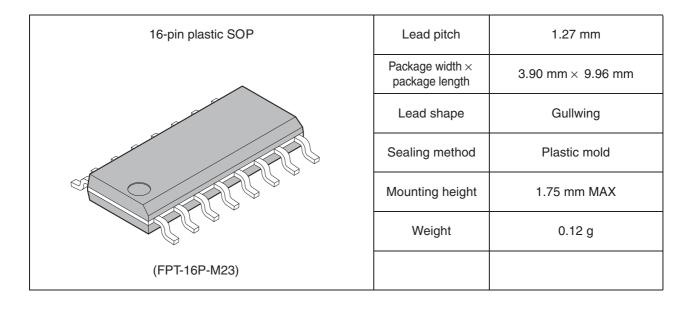
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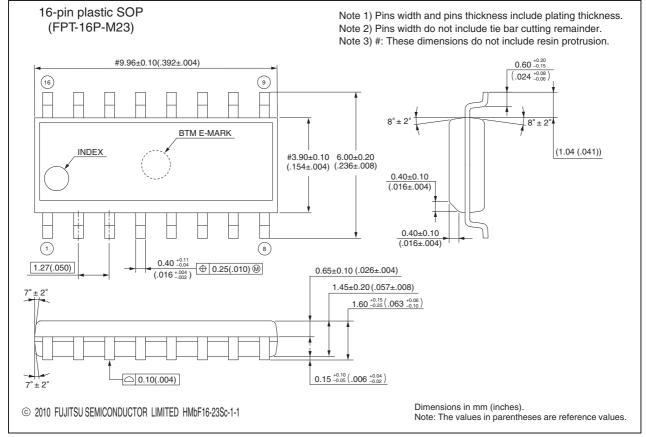
Please check the latest package dimension at the following URL. http://edevice.fujitsu.com/package/en-search/

16-pin plastic TSSOP	Lead pitch	0.65 mm
State Carlos Car	Package width \times package length	4.40 mm × 4.96 mm
	Lead shape	Gullwing
	Sealing method	Plastic mold
	Mounting height	1.20 mm Max
	Weight	0.06 g
(FPT-16P-M08)		



Please check the latest package dimension at the following URL. http://edevice.fujitsu.com/package/en-search/

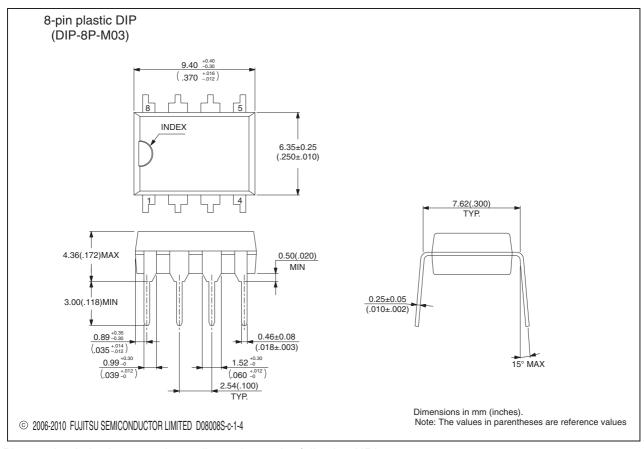




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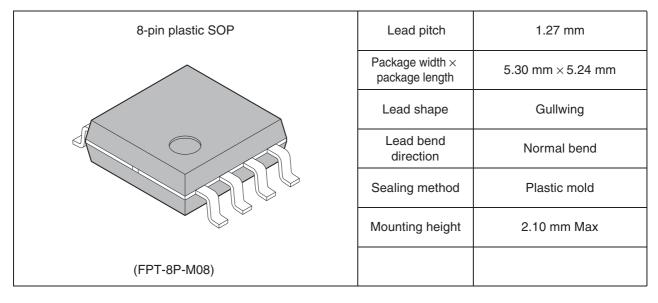
Please check the latest package dimension at the following URL. http://edevice.fujitsu.com/package/en-search/

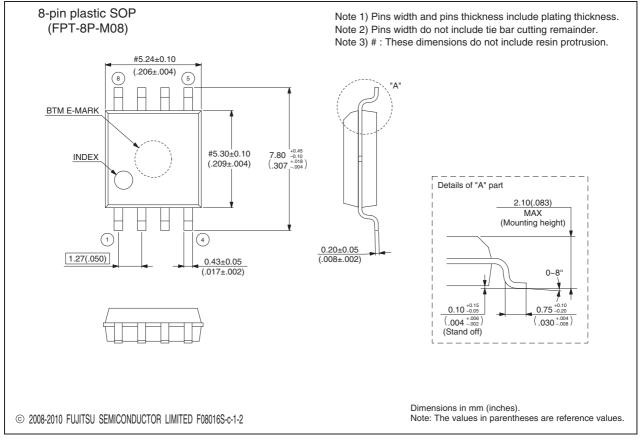
8-pin plastic DIP	Lead pitch	2.54 mm
	Sealing method	Plastic mold
(DIP-8P-M03)		



Please check the latest package dimension at the following URL. http://edevice.fujitsu.com/package/en-search/

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Please check the latest package dimension at the following URL. http://edevice.fujitsu.com/package/en-search/

■ MAJOR CHANGES IN THIS EDITION

A change on a page is indicated by a vertical line drawn on the left side of that page.

Page	Section	Details
5	PRODUCT LINE-UPMB95570H Series	Added the package DIP-8P-M03.
8	 PACKAGES AND CORRESPONDING PRODUCTS MB95560H Series 	Added the package DIP-8P-M03.
	 PACKAGES AND CORRESPONDING PRODUCTS MB95570H Series 	Added the package DIP-8P-M03.
	 PACKAGES AND CORRESPONDING PRODUCTS MB95580H Series 	Added the package DIP-8P-M03.
11	■ PIN ASSIGNMENT	Added the package DIP-8P-M03 to the pin assignment diagram of the MB95570H Series.
12	 PIN FUNCTIONS (MB95560H Series, 32 pins) 	Revised the function of the C pin. Capacitor connection pin \rightarrow
		Decoupling capacitor connection pin
14	 PIN FUNCTIONS (MB95560H Series, 20 pins) 	Revised the function of the C pin. Capacitor connection pin \rightarrow
		Decoupling capacitor connection pin
16	 PIN FUNCTIONS (MB95570H Series, 8 pins) 	Revised the function of the C pin. Capacitor connection pin \rightarrow
		→ Decoupling capacitor connection pin
17	 PIN FUNCTIONS (MB95580H Series, 32 pins) 	Revised the function of the C pin. Capacitor connection pin \rightarrow
		Decoupling capacitor connection pin
19	 PIN FUNCTIONS (MB95580H Series, 16 pins) 	Revised the function of the C pin. Capacitor connection pin
		Decoupling capacitor connection pin
24	PIN CONNECTIONC pin	Revised "smoothing capacitor" to "decoupling capacitor".
29	■ I/O MAP (MB95560H Series)	Corrected the initial value of the PLLC register. $0000000_B \rightarrow 000X0000_B$
31		Corrected the initial value of the CRTDA register. 00011111 _B \rightarrow 000XXXXX _B
33	■ I/O MAP (MB95570H Series)	Corrected the initial value of the PLLC register. $0000000_B \rightarrow 000X0000_B$
		Deleted all details of the PUL6 register.
35		Corrected the initial value of the CRTDA register. 00011111 _B \rightarrow 000XXXXX _B

Page	Section	Details
36	■ I/O MAP (MB95580H Series)	Corrected the initial value of the PLLC register. $0000000_B \rightarrow 000X000_B$
		Deleted all details of the PUL6 register.
38		Corrected the initial value of the CRTDA register. 00011111 _B \rightarrow 000XXXXX _B
42	 ELECTRICAL CHARACTERISTICS 1. Absolute Maximum Ratings 	Replaced IoL1 and IoL2 with IoL for the parameter ""L" level maximum output current".
		Revised the remarks of the parameter ""L" level average current".
		Replaced IoH1 and IOH2 with IOH for the parameter ""H" level maximum output current".
		Revised the remarks of the parameter ""H" level average current".
44	2. Recommended Operating Conditions	Revised "Smoothing capacitor" to "Decoupling capacitor" in the Parameter column and note *3.
45	3. DC Characteristics	Deleted P12 from the pins of V_{OL2} for the parameter ""L" level output voltage".
46, 47		Revised specifications of the parameter "Power supply current".
47		Added INSTBY to the parameter "Power supply current".
48	4. AC Characteristics (1) Clock Timing	Revised specifications of FCRH of the parameter "Clock frequency".
		Added FMCRPLL to the parameter "Clock frequency".
49		Corrected the minimum value of the parameter "Input clock pulse width" for the X0 pin and the X1 pin. $14.4 \rightarrow 12.4$
52	 4. AC Characteristics (2) Source Clock / Machine Clock Schematic diagram of the clock generation block 	Corrected the symbol and the clock name in the block of the main CR PLL clock. $F_{MPLL} \rightarrow F_{MCRPLL}$ Main CR PLL \rightarrow Main CR PLL clock
		Corrected the abbreviation of the clock mode select bits. SYCC2:RCS1, RCS0 \rightarrow SYCC:SCS[2:0]
62	4. AC Characteristics (7) Low-voltage Detection	Revised specifications of the parameter "Hysteresis width". Typ : $- \rightarrow 100$ Max : $100 \rightarrow -$
64	5. A/D Converter (1) A/D Converter Electrical Characteristics	Revised specifications of the parameters "Zero transition voltage", "Full-scale transition voltage" and "Compare time".
		Revised the minimum value of the parameter "Sampling time". 0.517 \rightarrow 0.6
65	5. A/D Converter (2) Notes on Using A/D Converter	Corrected the resistance for "2.7 V \leq Vcc < 5.5 V". 15.7 k $\Omega \rightarrow$ 5.7 k Ω



Page	Section	Details
68	 Flash Memory Program/Erase Characteristics 	Added the following note. *2: $V_{CC} = 2.4$ V, $T_A = +85^{\circ}C$, 100000 cycles
69 to 74	■ SAMPLING CHARACTERISTICS	Revised all sampling characteristics diagrams.
76, 77	ORDERING INFORMATION	Revised all part numbers.
77		Added part numbers of the package "8-pin plastic DIP (DIP-8P-M03)".
83	PACAKGE DIMENSION	Added the package diagram of DIP-8P-M03.



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